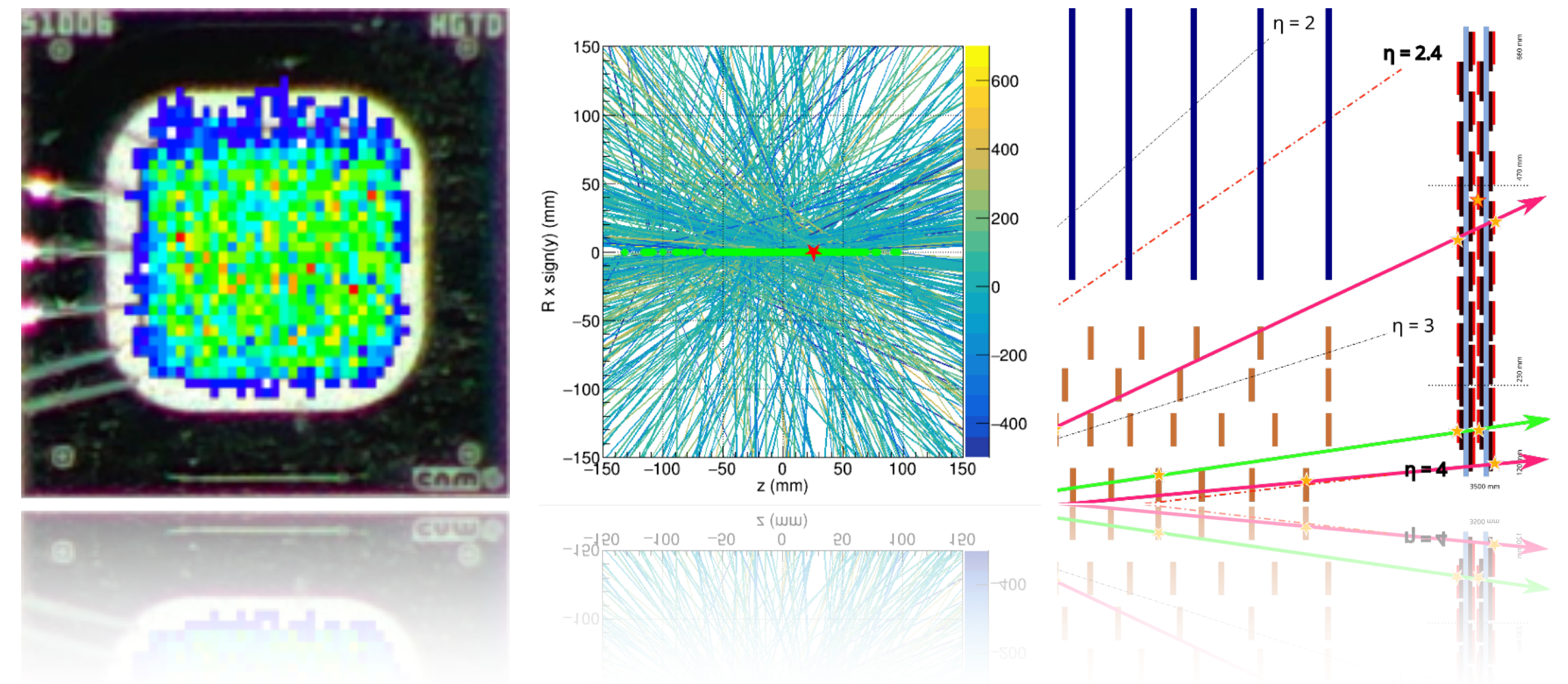


Pileup suppression with timing detectors

Mengqing Wu (*Radboud University & Nikhef*)
On behalf of the ATLAS HGTD group

LHCP 2024, Boston, Oct 3-7 2024



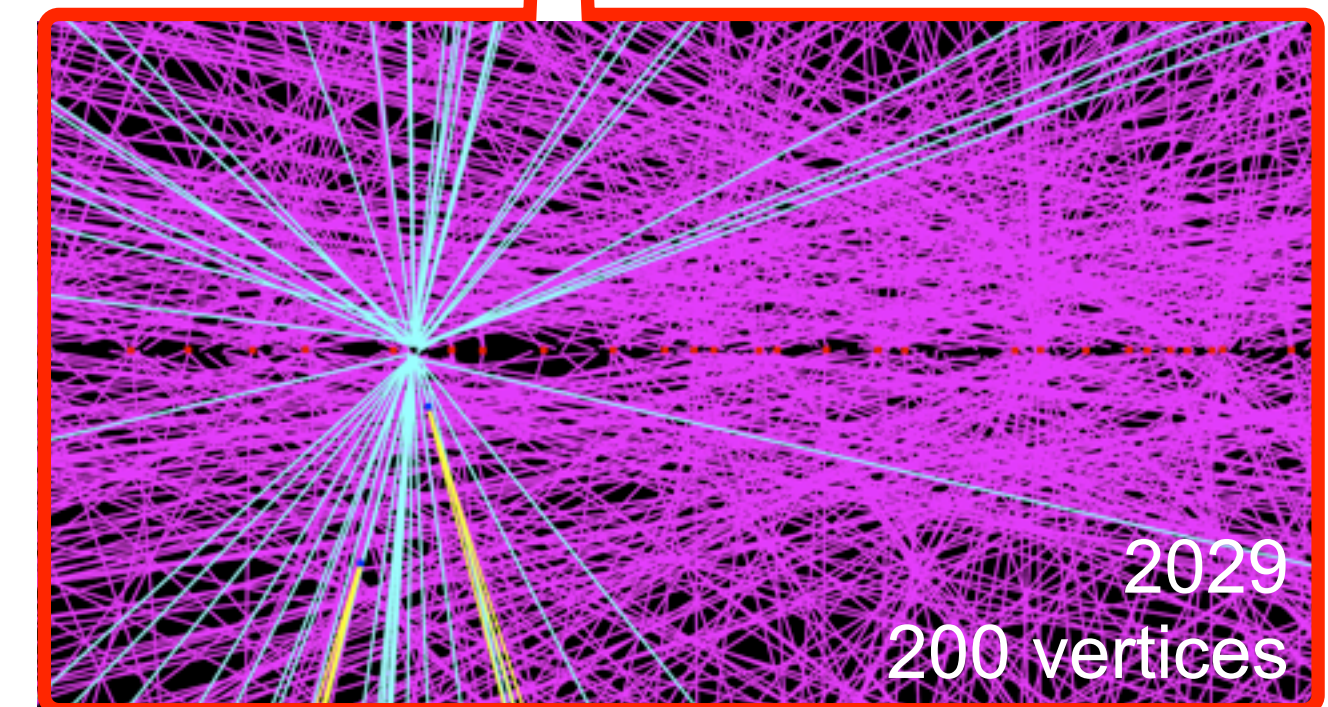
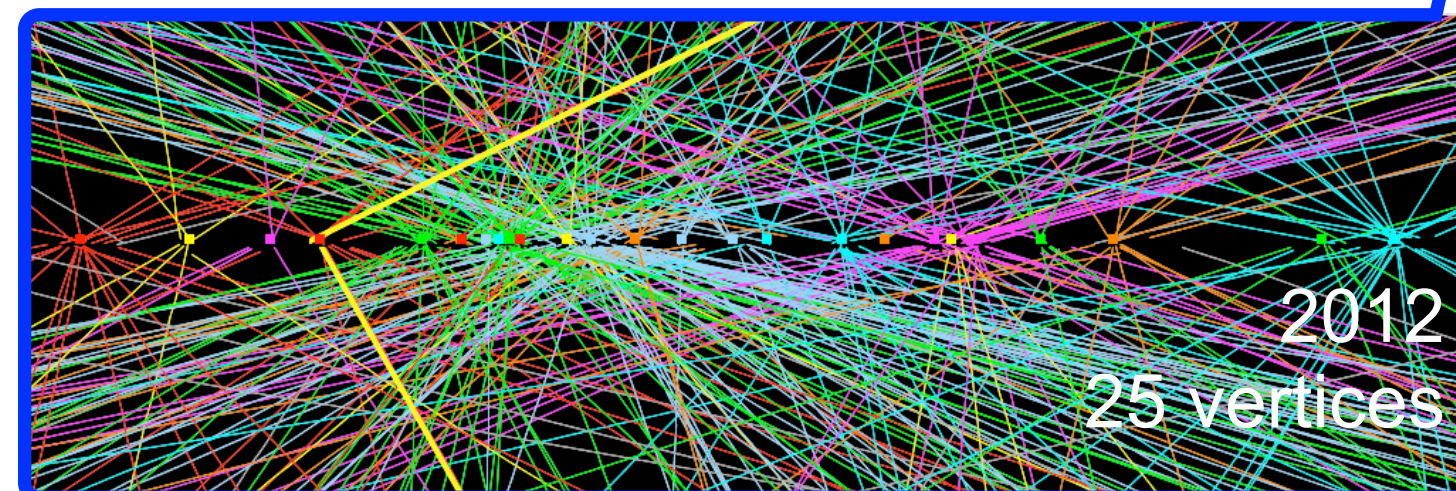
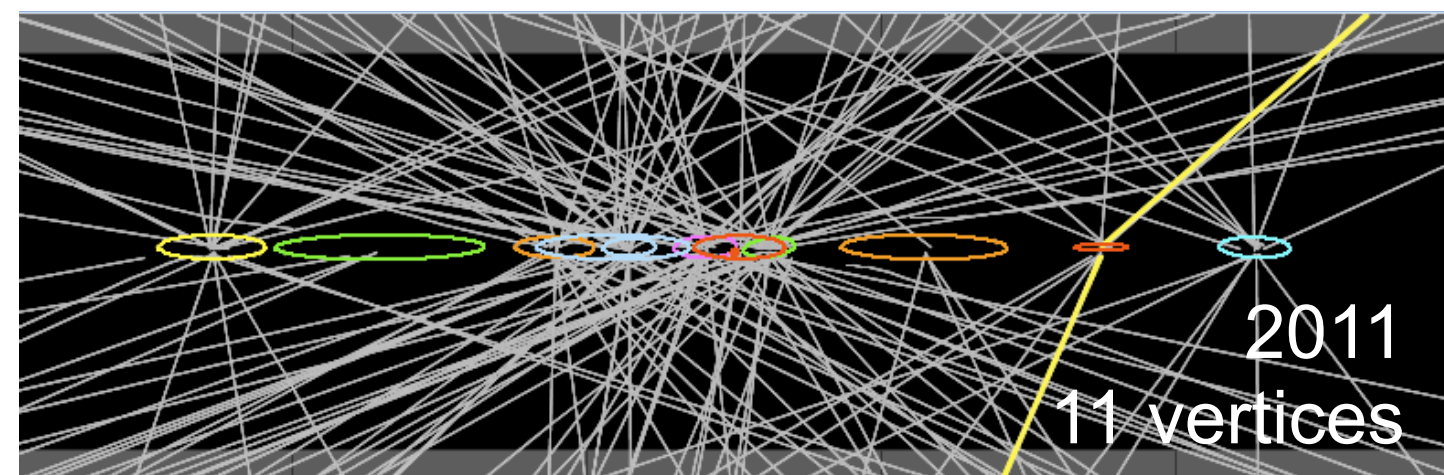
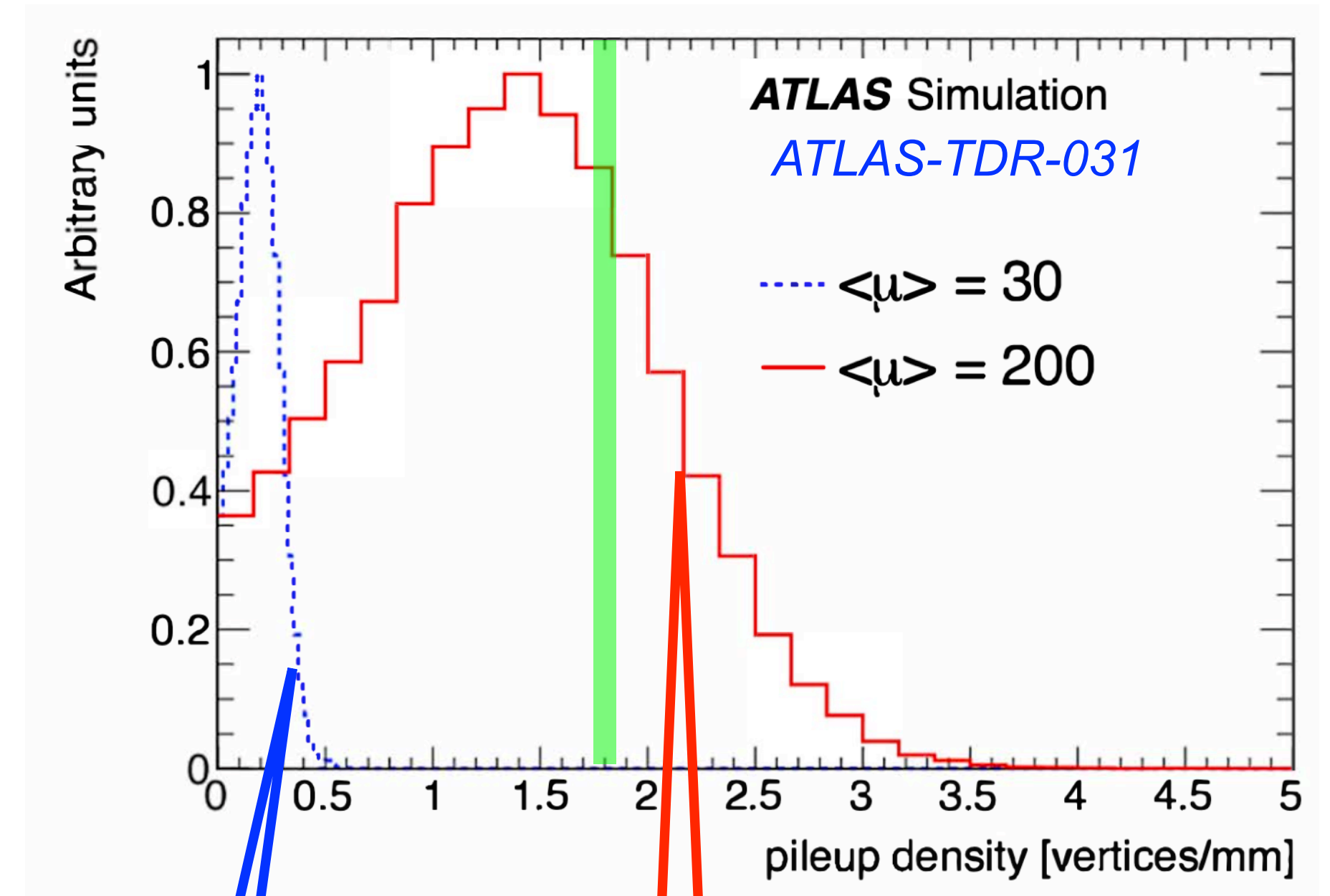
Challenges on Detectors at HL-LHC

High pileup challenge at HL-LHC, where instantaneous luminosity is **5 times higher**, giving a total integrated luminosity of up to 4 ab^{-1}

- up to average 200 inelastic pp collisions

Challenges on the detectors

- to separate the overlapped vertices and objects
→ **motivates** not only **finer spatial measurements (ITK)** but also **timing measurements (HGTD)**
- performance v.s. accumulated luminosity (*radiation hard*)



Exploit the 4th Dimension: Time

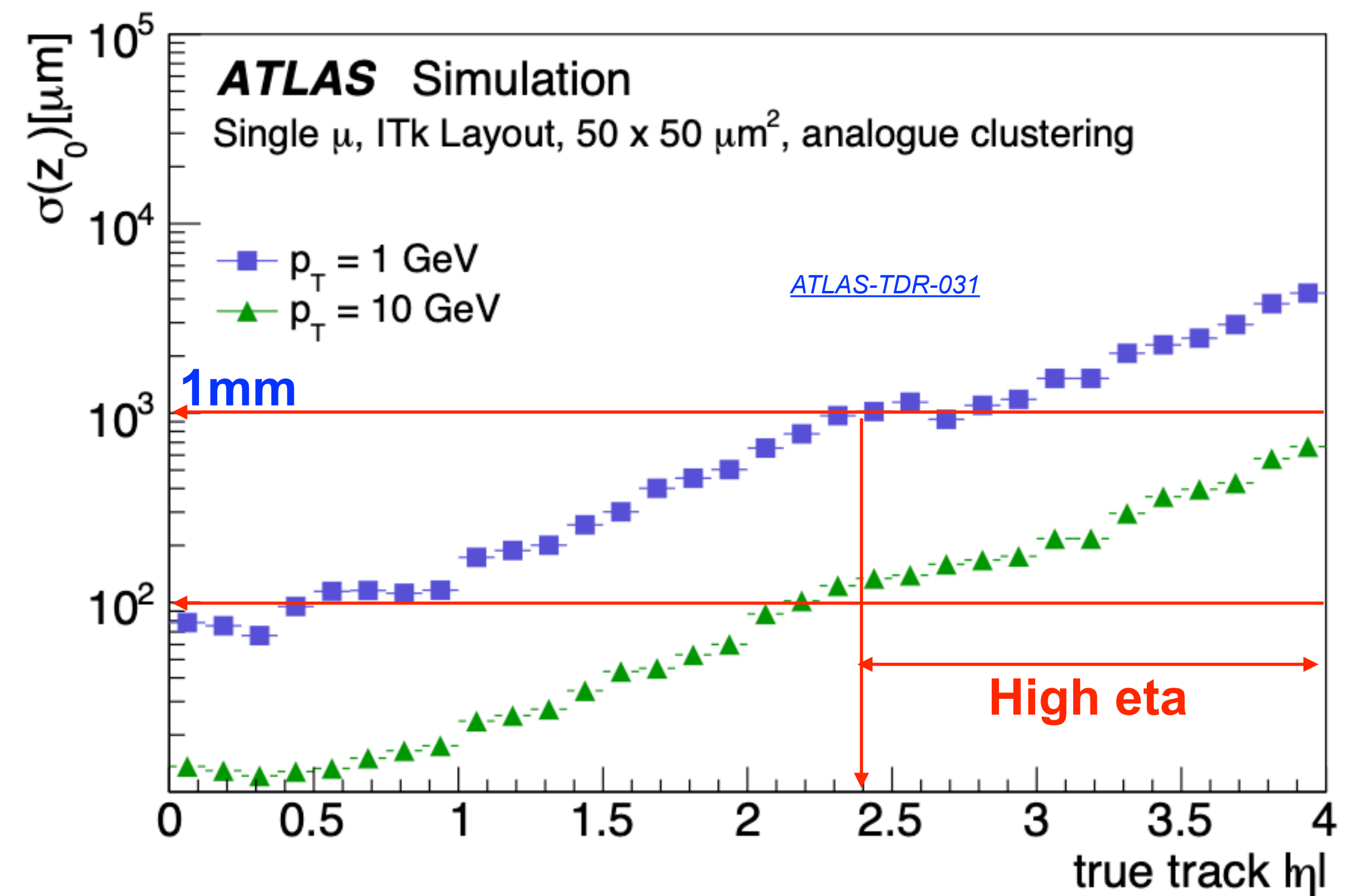
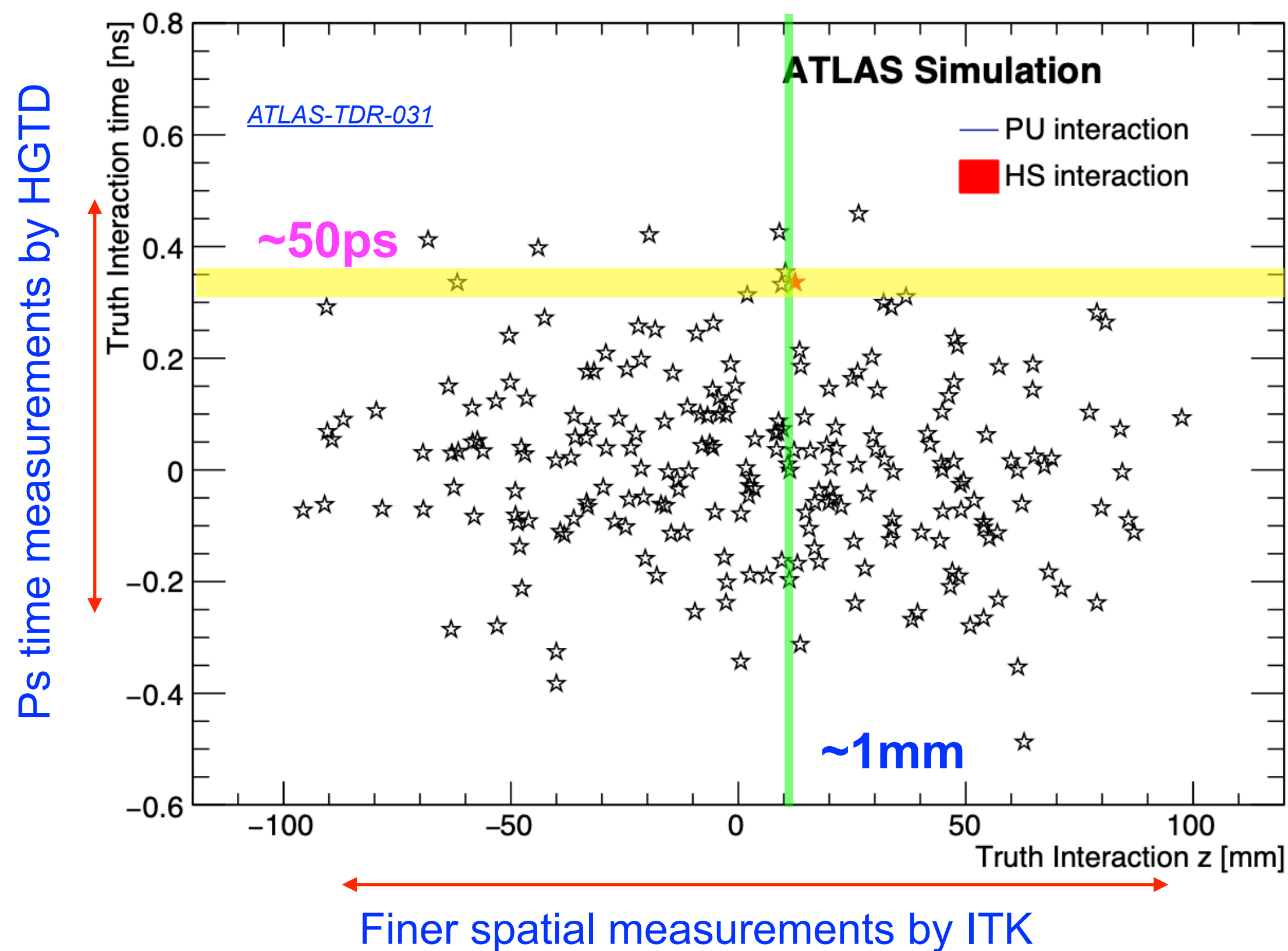
Interactions spread not only along z but also in t

(RMS ~ 175 ps), with $\sigma_t < 50$ ps

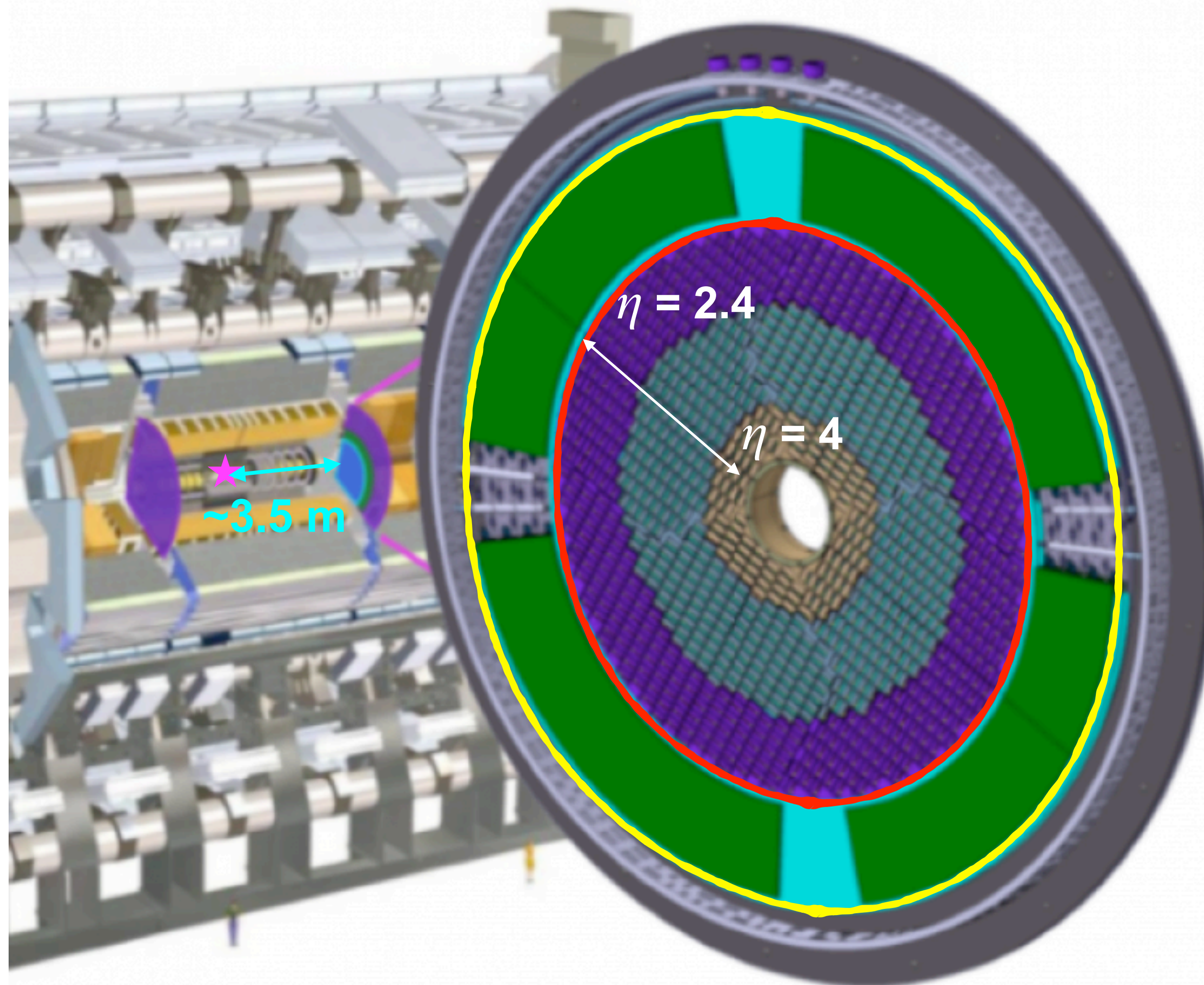
→ pile-up suppression by a factor of ~ 6

Timing is crucial to the success of the physics programme in **high $|\eta|$ region**

→ as impact parameter deteriorates with $|\eta|$



High Granularity Timing Detector



Pixelated detector providing **highly precise time** measurements < 50 ps in the forward region

- Four layers of sensors (different overlap depending on the radius): **1 - 4 hits per track**
- Precise **luminosity** measurements with 1% luminosity uncertainty (bunch-by-bunch 40MHz readout - very challenging readout design)

Detector specs:

More luminosity see [Simone's talk on Friday](#)

- $|z| \sim 3.5$ m from the nominal interaction point (installed in the gap between barrel and end-cap calorimeter)
- Forward region: $2.4 < |\eta| < 4.0$
- Radiation hard up to:
 2.5×10^{15} n_{eq}/cm² (w/ Safety Factor=1.5) for sensor;
2 MGy (w/ Safety Factor=2.25) for electronics.

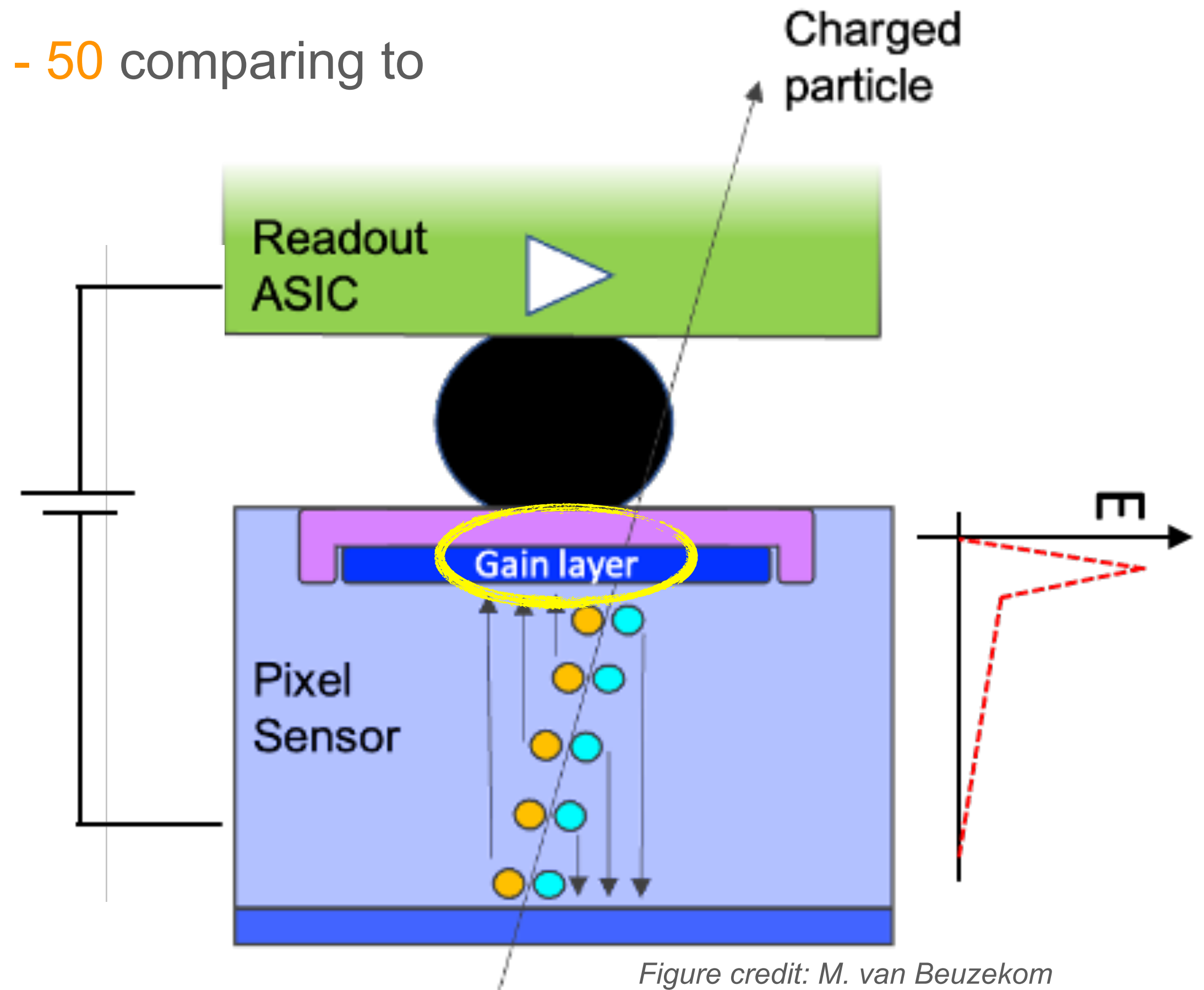
Low Gain Avalanche Diode

Low Gain Avalanche Diodes (LGAD) - a **novel silicon sensor** technology

- Key feature - **the gain layer**, providing a modest **gain of 10 - 50** comparing to APD and SiPM (*radiation deteriorates the gain*)
- Picosecond fast timing features (*intrinsic sensor timing constant*): **high drifting velocity** (fast, gain), **thin active layer** (fast), meanwhile large signal (gain, σ_t).

HGTD LGAD geometry

- Thin: **50 μm thick**
 - Compromise between Landau fluctuations contributing to the time resolution, charge/bias property etc.
- Pad size: **1.3 x 1.3 mm^2**
 - Compromise between rise time, capacitance, occupancy, fill factor...
- Strong signals: **10 fC (w/ 20 gain)** unirradiated and **4 fC (w/ 8 gain)** end-of-life



Single Hit Time Measurement - Readout Electronics

Time Resolution is dominant by three components*

$$\sigma_t^2 = \sigma_{\text{TimeWalk}}^2 + \sigma_{\text{jitter}}^2 + \sigma_{\text{TDC}}^2$$

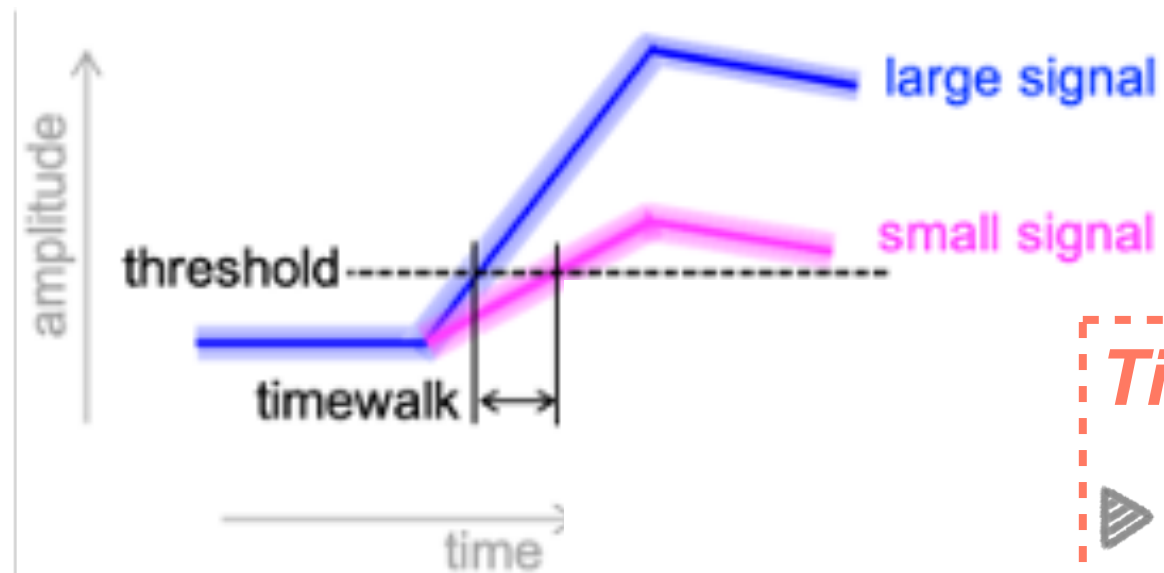


Figure credit: M. van Beuzekom

Time walk

- ▶ Time-of-Arrival (ToA) relates to the time when signal cross the threshold - thus depending on **signal magnitude** (energy loss Landau fluctuations) and **signal shape** (hit position)
- ▶ Compensation can be done by introducing **Time-over-Threshold (ToT)** measurement or using **Constant-Fraction-Discriminator (CFD)**
 - ▶ ToT is a common solution, while CFD is hard to be implemented at ASIC level

Requires:

- Low threshold
- Large signal S
- Short rise time t_r

* This equation has other variations, depending on how one categories the resource; the format here is commonly used in detector R&D community

Single Hit Time Measurement - Readout Electronics

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$$\sigma_t^2 = \sigma_{\text{TimeWalk}}^2 + \sigma_{\text{jitter}}^2 + \sigma_{\text{TDC}}^2$$

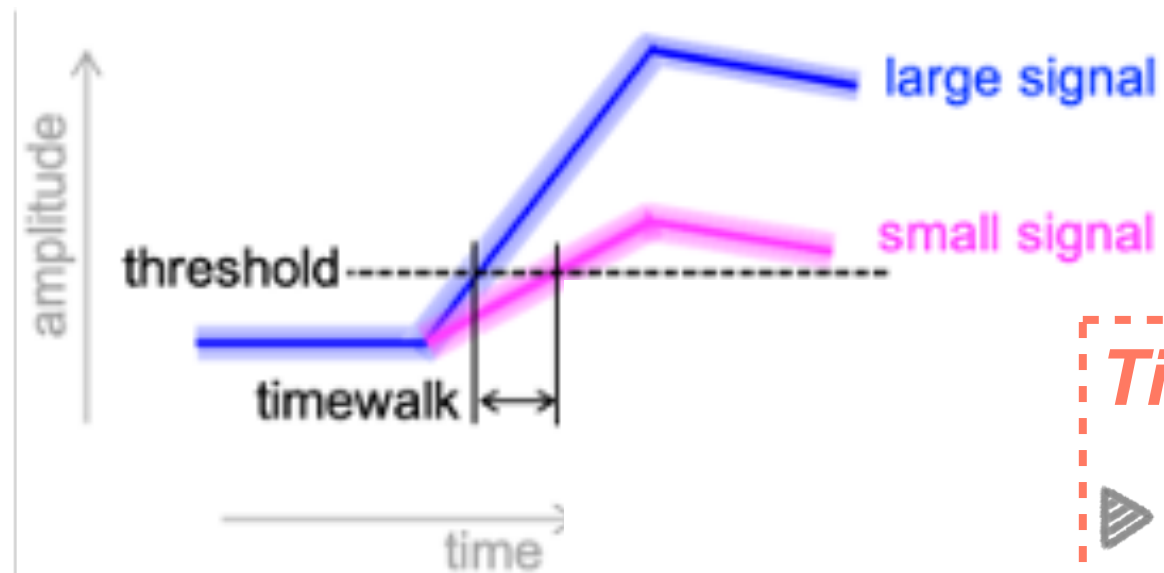


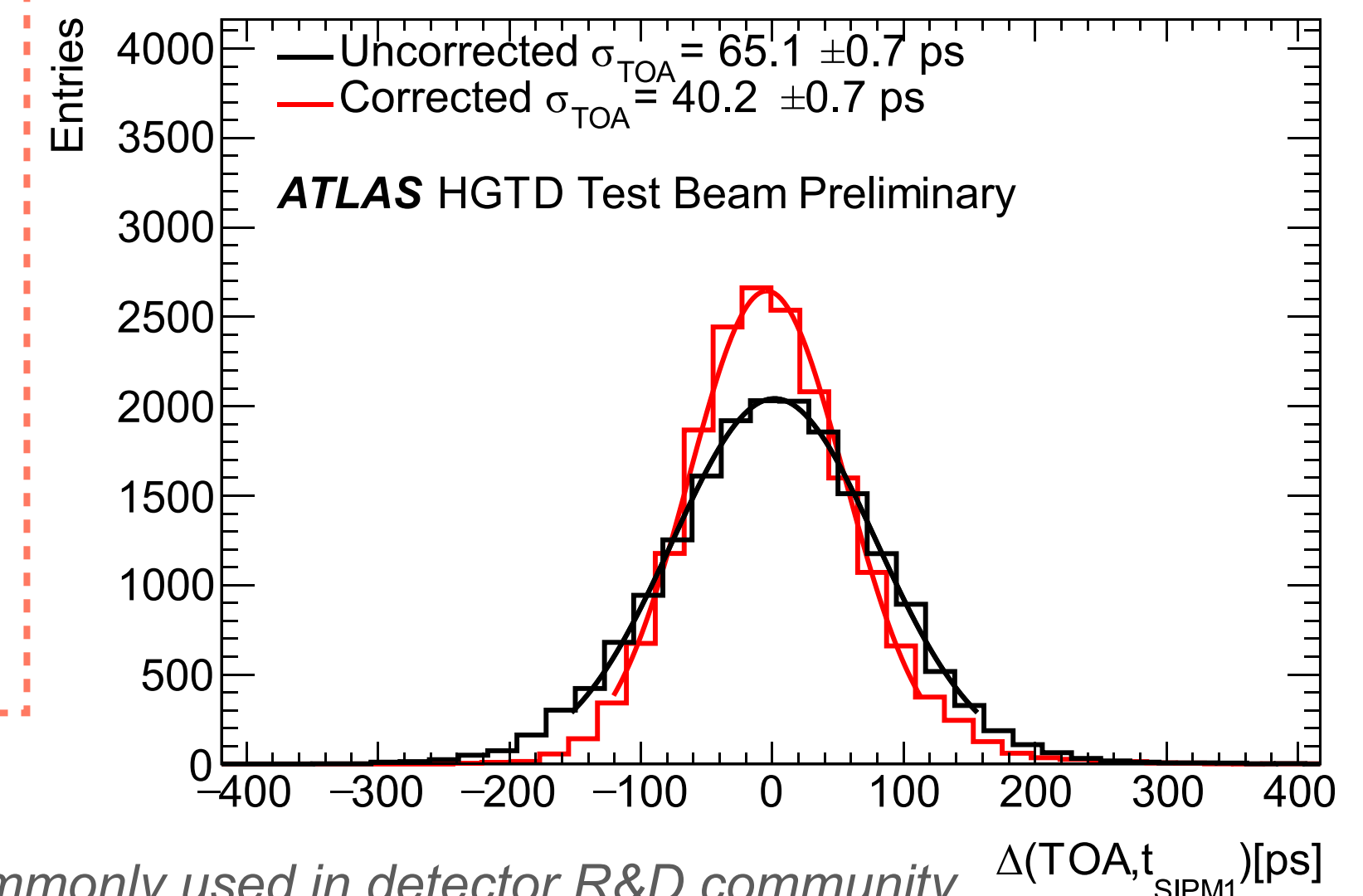
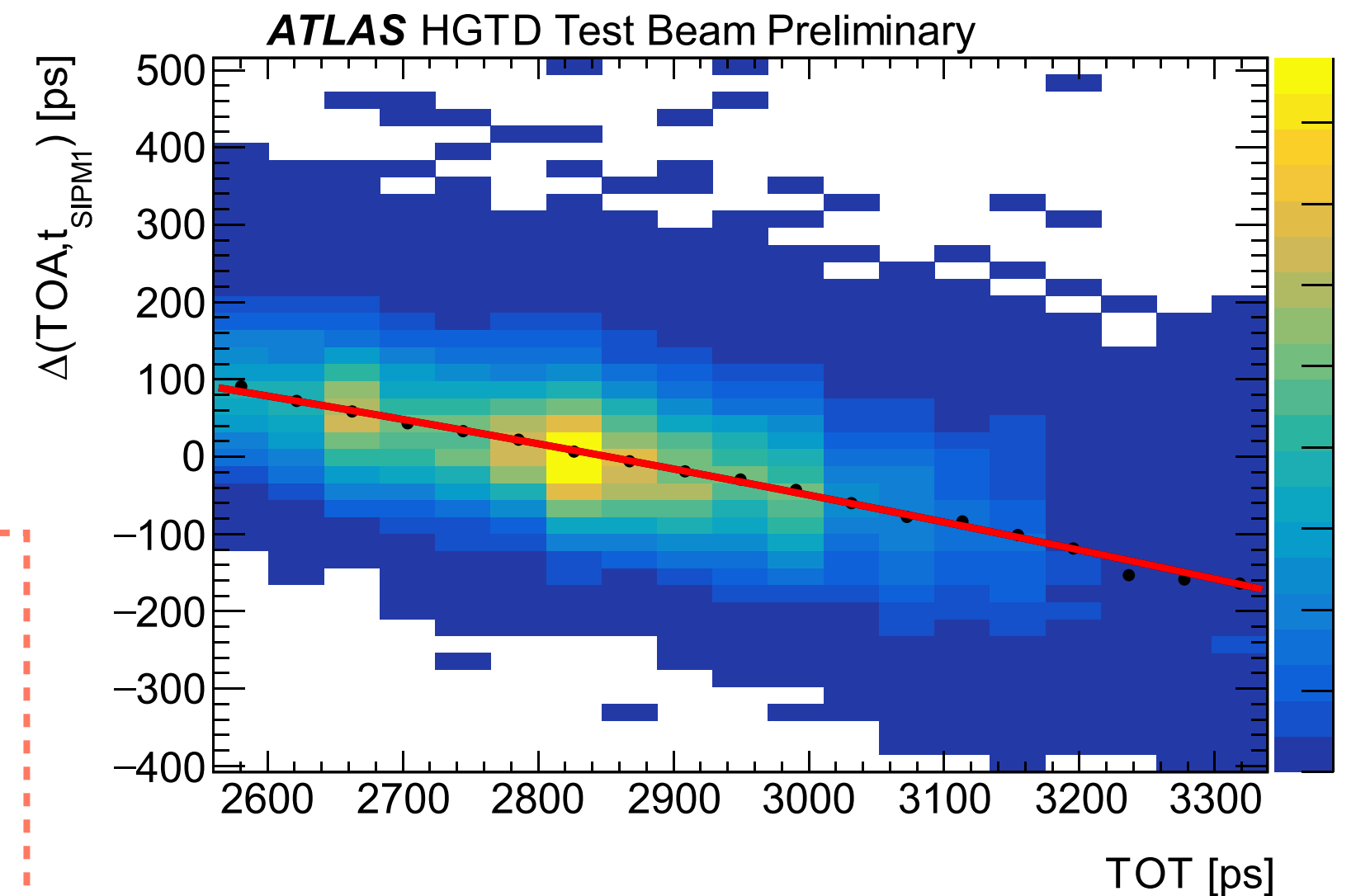
Figure credit: M. van Beuzekom

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- ▶ Compensation can be done by introducing **Time-over-Threshold (ToT)** measurement or using **Constant-Fraction-Discriminator (CFD)**
 - ▶ ToT is a common solution, while CFD is hard to be implemented at ASIC level
- ▶ HGTD TB results show: after Time-walk correction, unirradiated modules meet requirement of $\sigma_t < 50$ ps

Requires:

- Low threshold
- Large signal S
- Short rise time t_r



* This equation has other variations, depending on how one categories the resource; the format here is commonly used in detector R&D community

Single Hit Time Measurement - Readout Electronics

Time Resolution is dominant by three components*

Challenging to build such a readout system to fulfil the time requirement

$$\sigma_t^2 = \sigma_{\text{TimeWalk}}^2 + \sigma_{\text{jitter}}^2 + \sigma_{\text{TDC}}^2$$

Requires:

- ❑ Low threshold
- ❑ Large signal S
- ❑ Short rise time t_r

Can be corrected/
compensated

Requires:

- ❑ High Signal-to-Noise
- ❑ Short rise time t_r

Largest component
Depending on detector geometry
and system electronic noise

TDC Granularity (bin size)
& reference clock stability, requiring

- ❑ Trade-off: fine TDC binning \equiv power hunger
- ❑ High clock performance: stability and jitter

Overall clock distribution
needs to be < 15 ps

It is important to notice that, **intrinsic sensor contribution** (geometry, technology driven) is **NOT** discussed here, **partial sensor contribution** is considered under the *TimeWalk* term in this function.

* This equation has other variations, depending on how one categories the resource; the format here is commonly used in detector R&D community

Challenges of Event Reconstruction

Challenges in track-to-vertex association and track-to-object association:

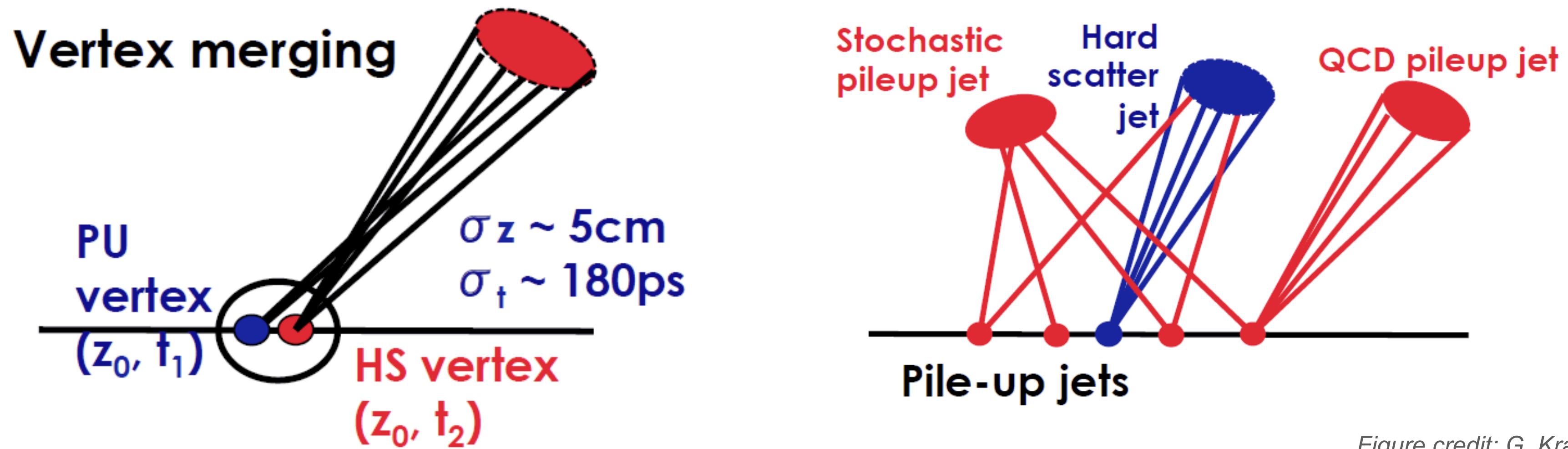


Figure credit: G. Kramberger

Adding time to track-to-vertex association

- **Spatial-based association:** track z_0 geometrically compatible in z-axis with respect to the vertex position

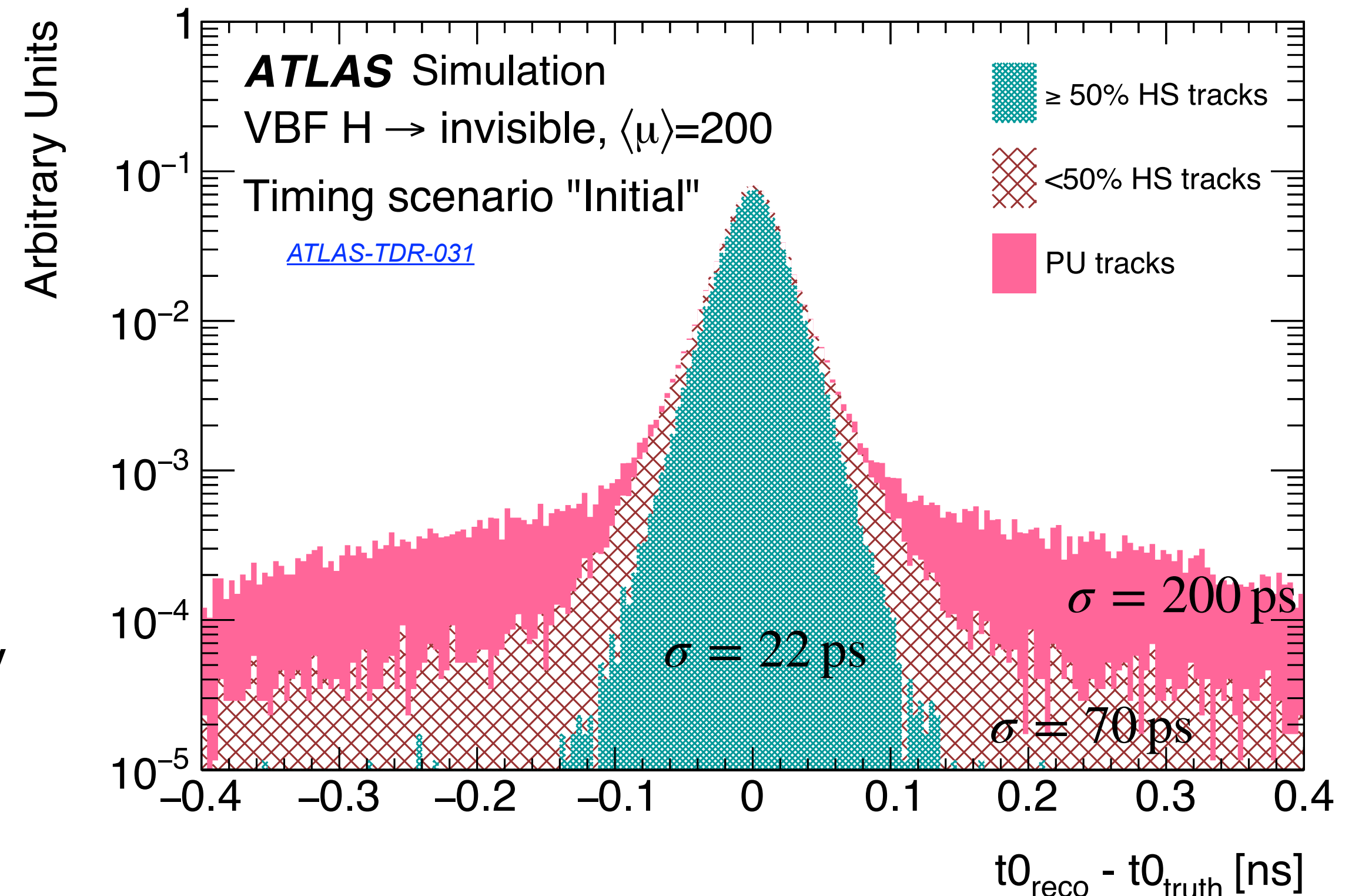
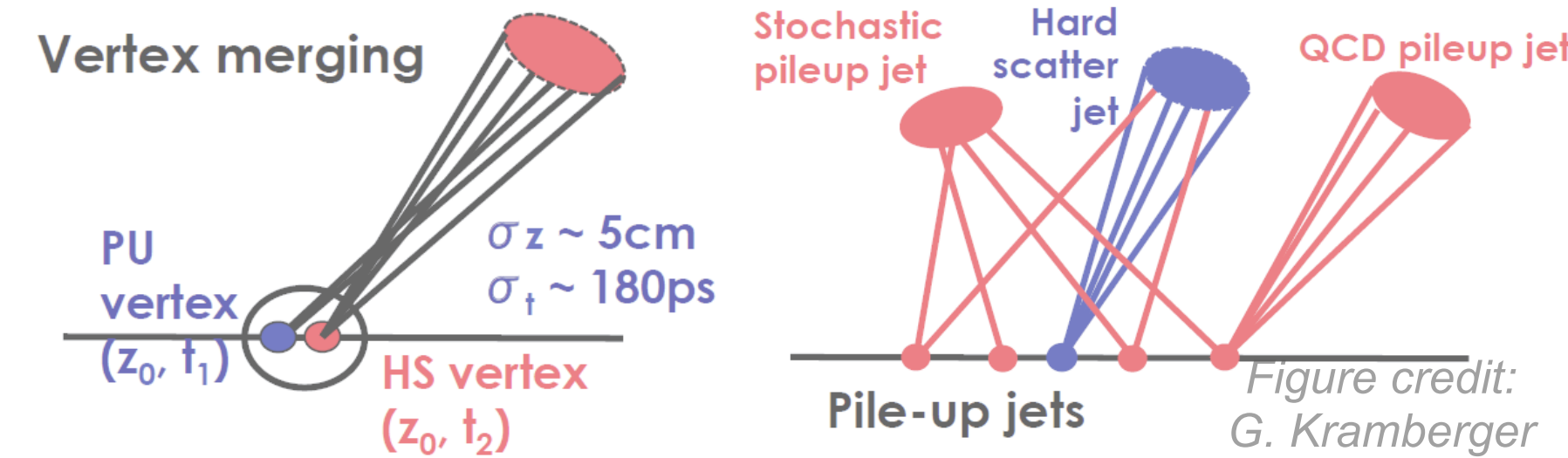
$$\frac{|z_0 - z_{\text{vertex}}|}{\sigma_{z_0}} < s = 2.5 \quad (3)$$

- Additional **time-based association:**

- If knowing the hard scatter (HS) vertex time t_0

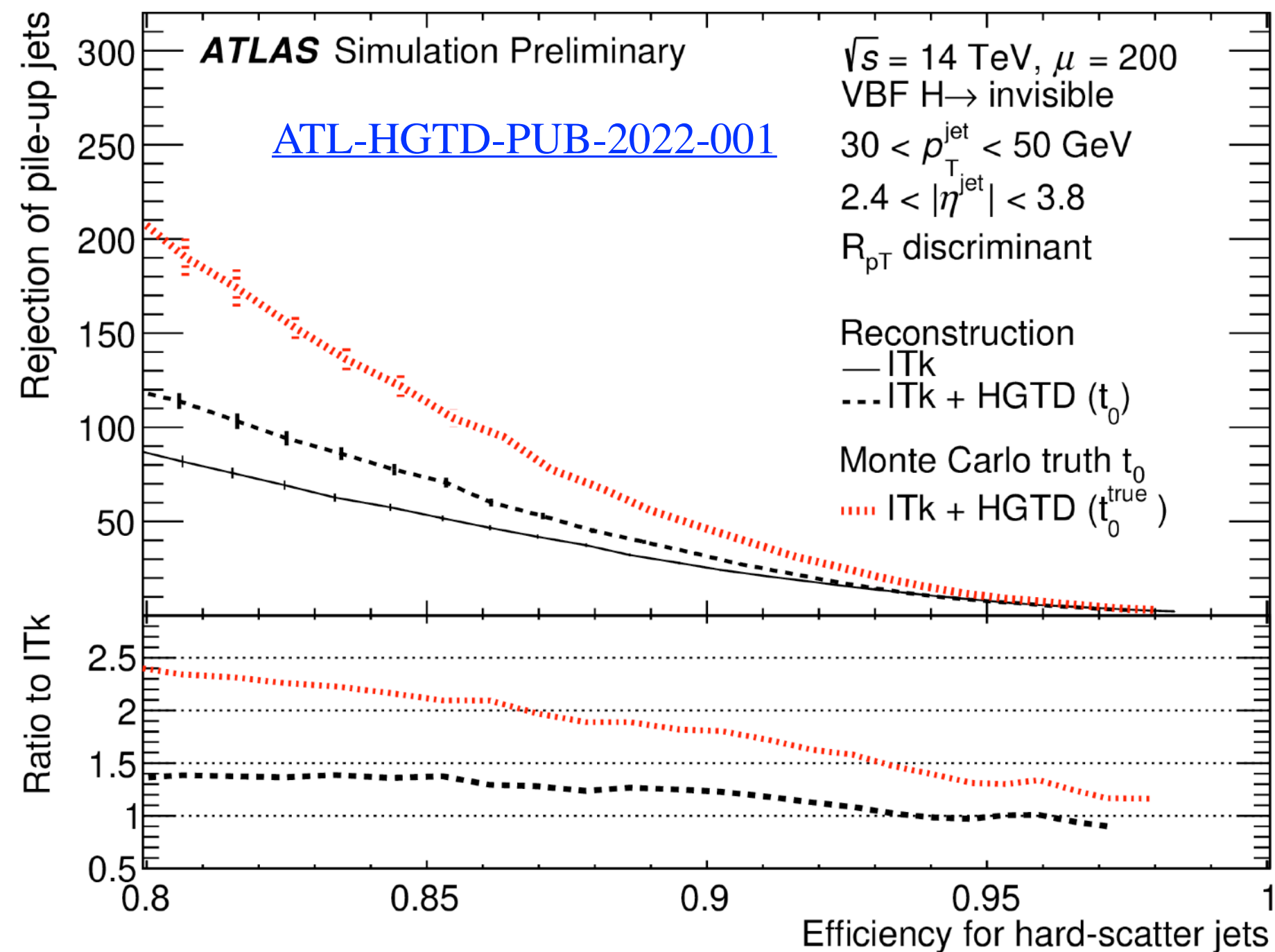
$$\frac{|t_{\text{trk}} - t_0|}{\sigma_t} < s = 2 \quad (3)$$

- **Challenging t_0 determination:** (1) limited $|\eta|$ coverage; (2) HS vertex t_0 measurement built upon the prior track-to-vertex association
- If t_0 unknown: so-called *self-tagging* approach - for given reconstructed object, check time consistency to clean/remove time incompatible components



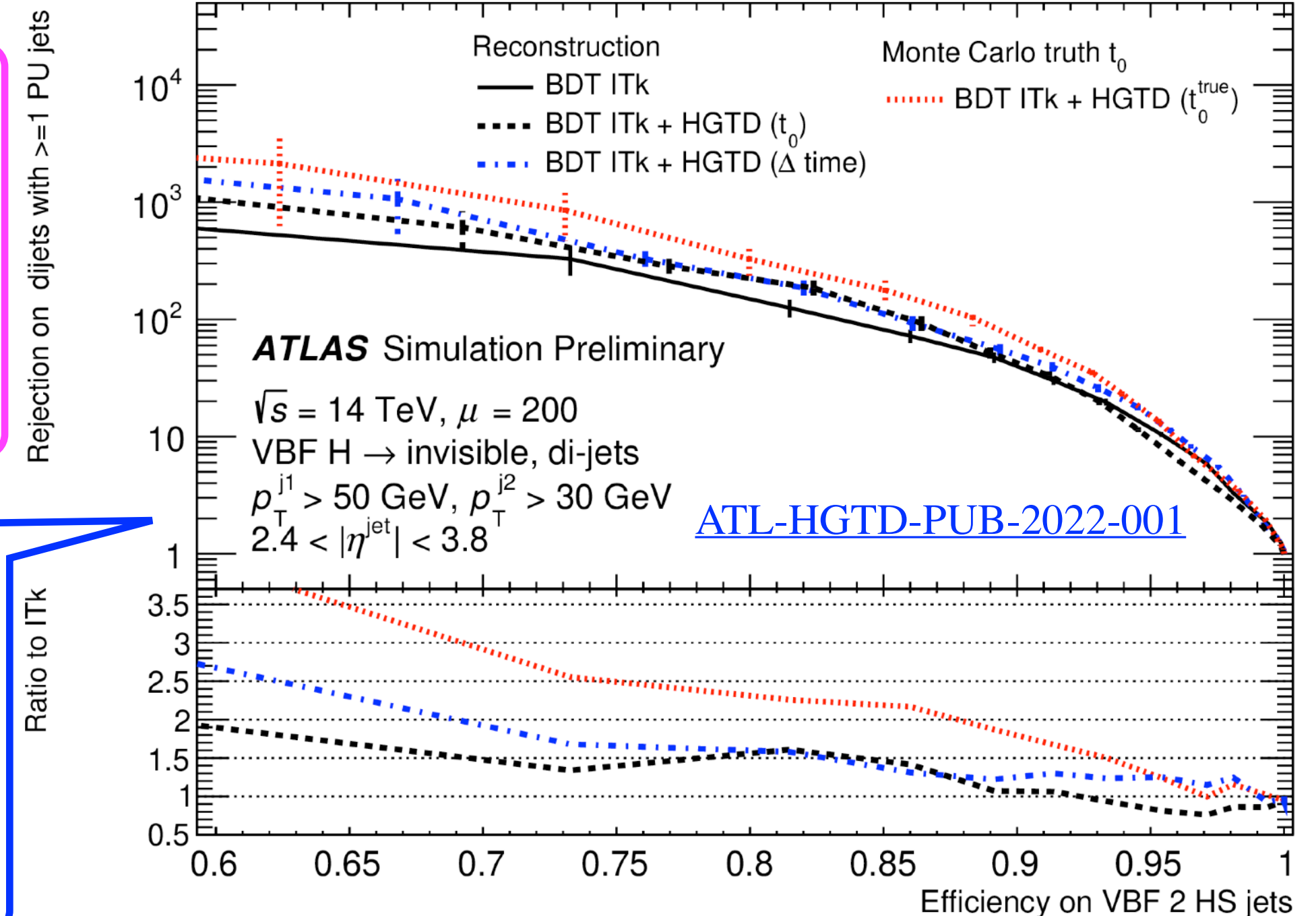
Adding time to suppress pile-up jets

Use the *self-tagging* approach to reduce pile-up track contamination thus improving discriminant variables such as R_{P_T} (JHEP 04 (2008) 063) and JVF (ATLAS-CONF-2014-018) for the jet-vertex tagging



R_{P_T} : scalar P_T sum of all tracks that are inside the jet cone and originate from the HS vertex, divided by the fully calibrated jet p_T

JVF: scalar p_T sum of tracks that associate to jet and originate from the HS vertex, divided by the scalar p_T sum of all associated tracks



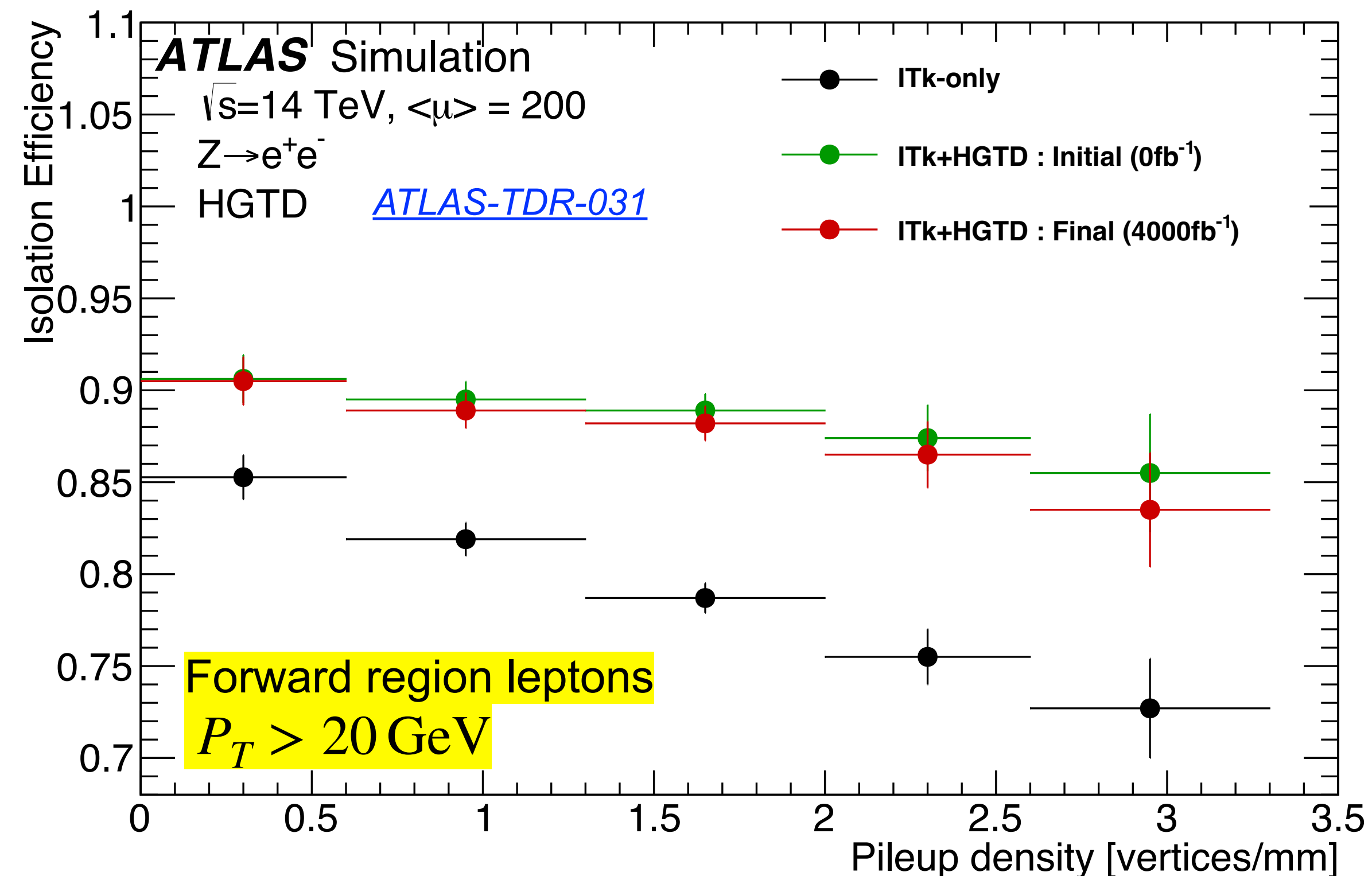
Taking ITK only scenario as benchmark to see how HGTD time measurement adds.

Pile-up jet tagging improves by up to 40% for low P_T forward jets.

Double pile-up jet tagging is up to 1.9-2.7 times better → Good potential for a VBF/VBS HLT using HGTD.

Adding time to improve electron isolation efficiency

- The efficiency of *track-based lepton isolation* $\epsilon(P_T^{\text{iso}})$ is defined as the **probability** that no additional track with $P_T > 1 \text{ GeV}$ is within a cone of $\Delta R = 0.2$ from the electron track
- This variable is sensitive to pile-up density
 - can be recovered by applying a time consistency criterion to reduce the pile-up track contamination in the isolation cone
- With time: this efficiency is improved by about 10% for local pile-up density at 1.6 vertices/mm (*mean value at HL-LHC*)
- Further confirms the impact of pile-up suppression with time at physics object level



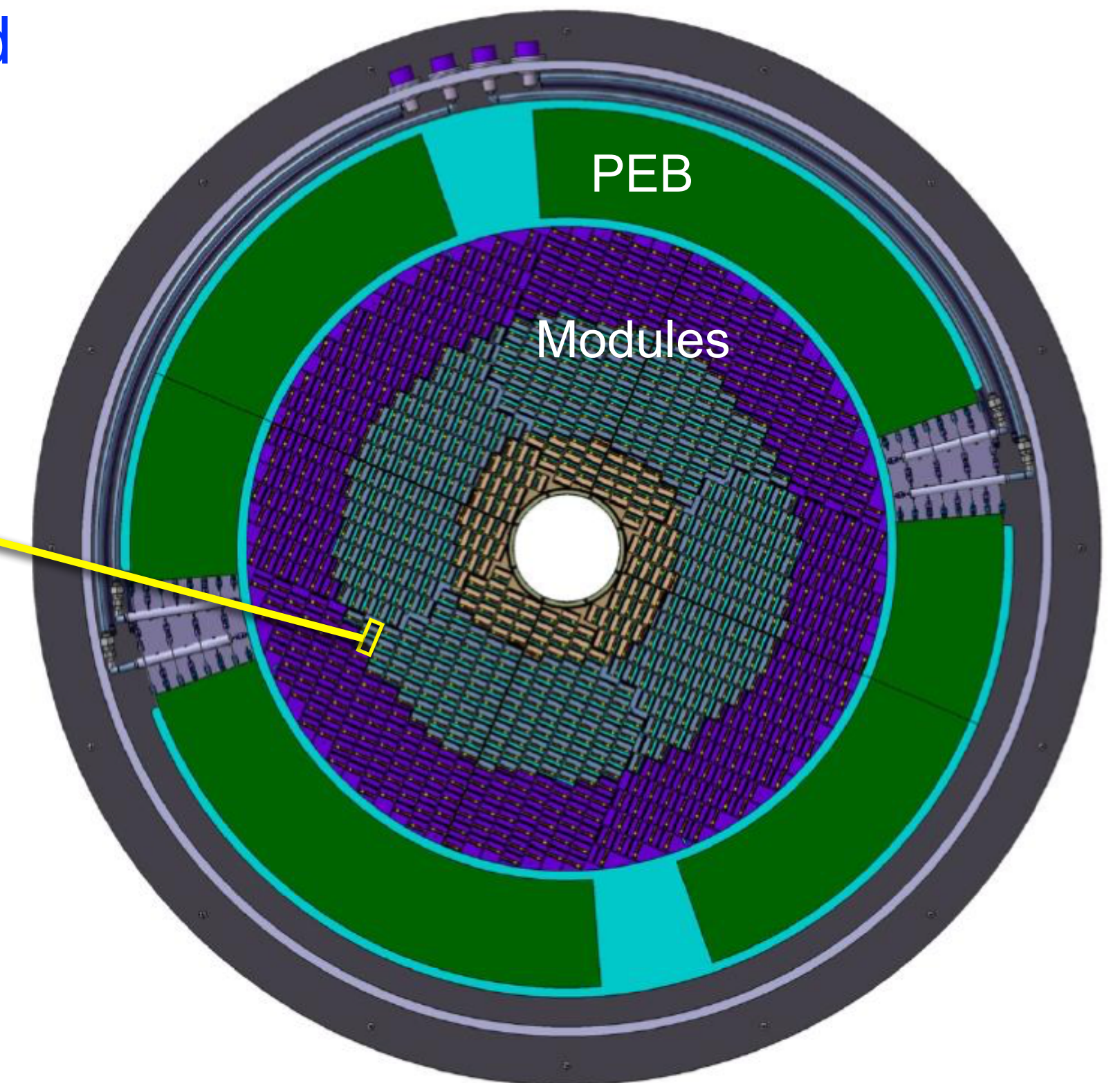
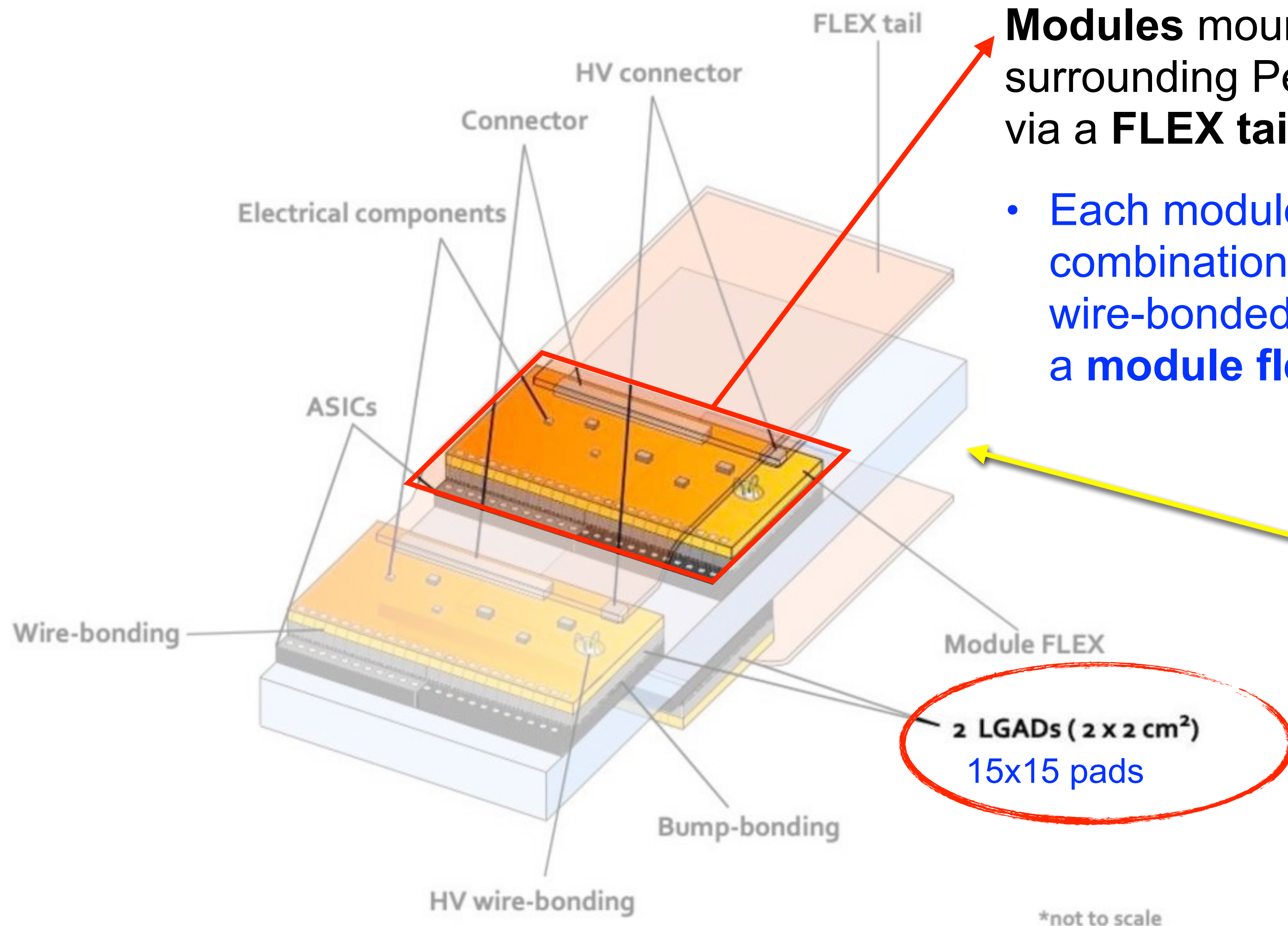
Conclusion and outlook

- The significantly increased instantaneous luminosity impose **a great challenge on distinguishing the overlapped vertices and physics objects**
 - **additional precise timing measurement helps**, especially in the forward region where impact parameter measurements deteriorate.
 - **HGTD based on LGAD technology** is under construction **to provide a track time measurement with a resolution better than 50 ps in the forward region $2.4 < |\eta| < 4$ and a precise luminosity measurement** (which can be vital as HL-LHC physics goals is dominant by precision measurements)
- **Challenges on building such a detector** to achieve a better than 50ps time resolution
 - **The LGAD sensor needs to meet the radiation hardness requirement while providing an intrinsic time resolution better than 50ps**
 - Besides, **the entire readout electronic chain needs to fulfil time requirement** - various development challenges to tackle to mitigate effects of time walk, noise jitter and TDC.

Backup

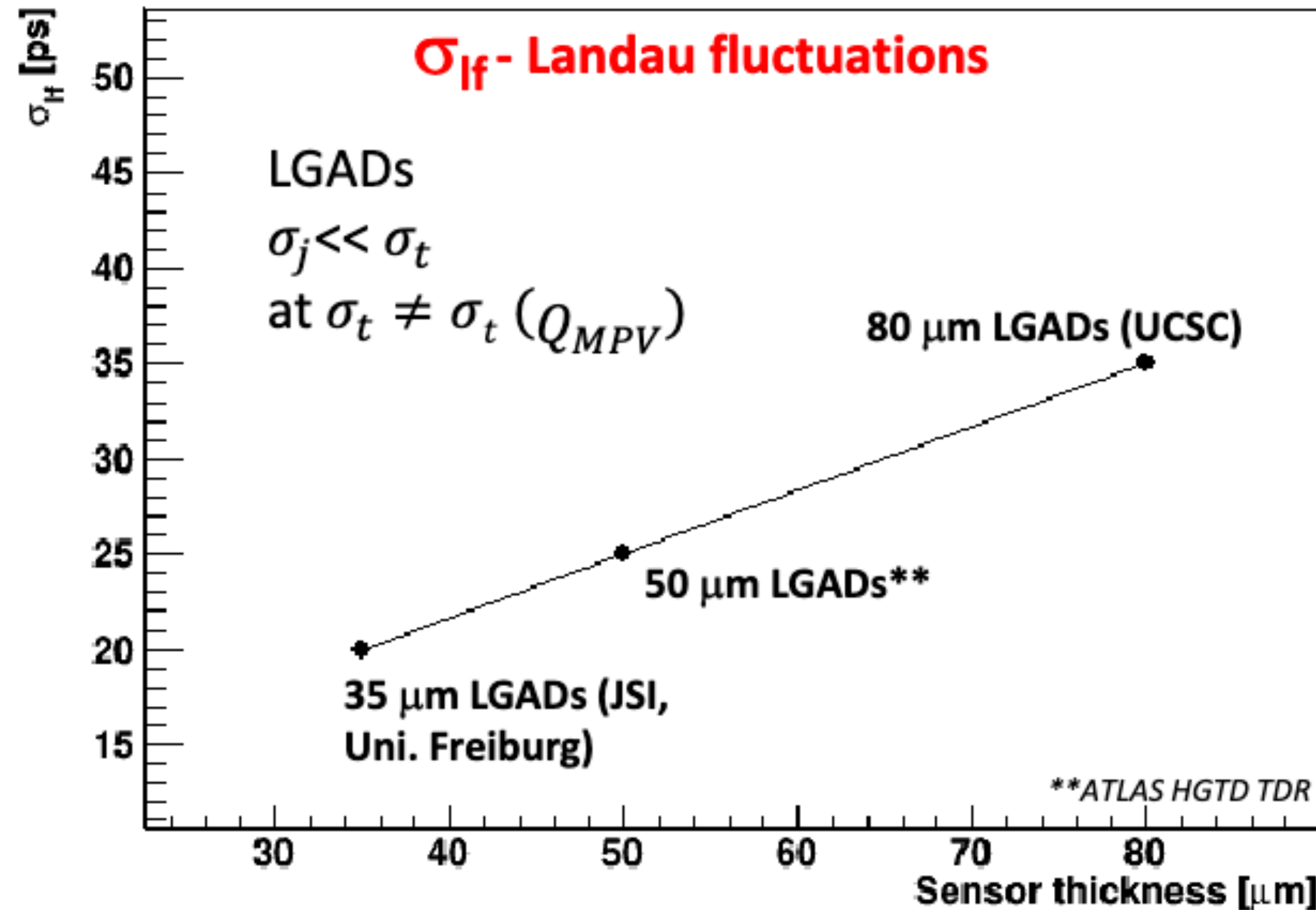
You've got one

HGTD Zoom-in: Detector Module



Choice of detector geometry

Slide from G. Kramberger



Active thickness ~ 50 (+/-5) μm

- large capacitance (noise) can be offset by gain \rightarrow good S/N
- In order to reach the desired time resolution the thickness is limited to $< 80 \mu\text{m}$ (Landau fluctuations)
- thinner sensors have steeper Q-V (difficult to control the bias voltage over a single module)

Cell size $1.3 \times 1.3 \text{ mm}^2$ determines:

- capacitance (dominated by capacitance to the back, inter-pixel capacitance $\sim 0.5 \text{ pF}$ – measured and shown at PDR)
- assures that weighting field is $1/\text{thickness}$ and that the role in contribution to the time walk is negligible – dominated by the σ_{lf}
- pixel hit occupancy and fill factor (indirectly)

$$\sigma_t^2 = \sigma_j^2 + \sigma_{tw}^2 + \sigma_{TDC}^2$$

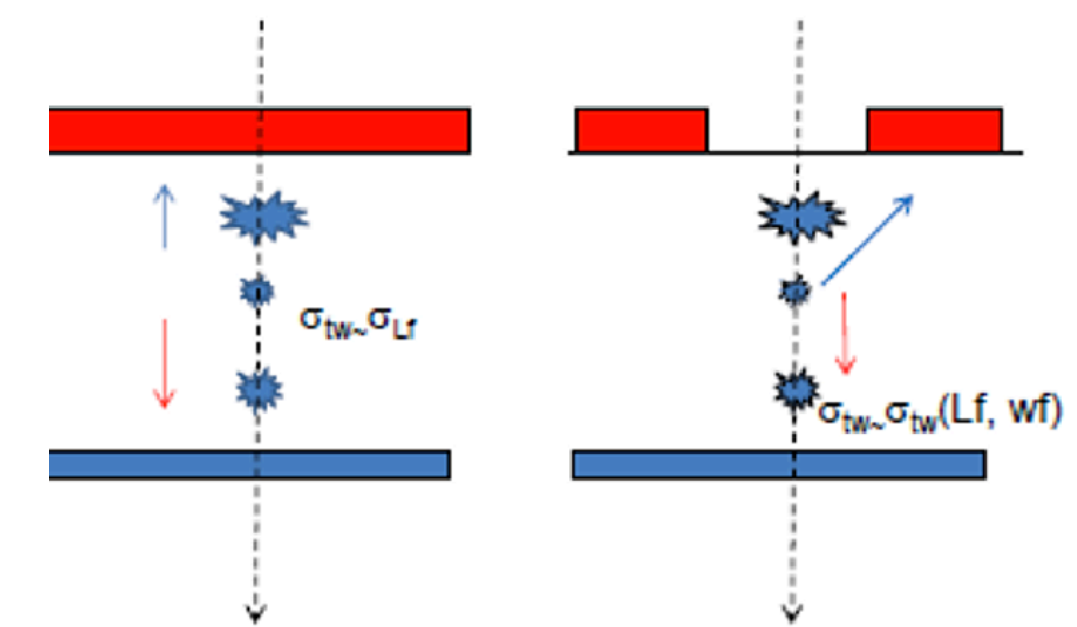
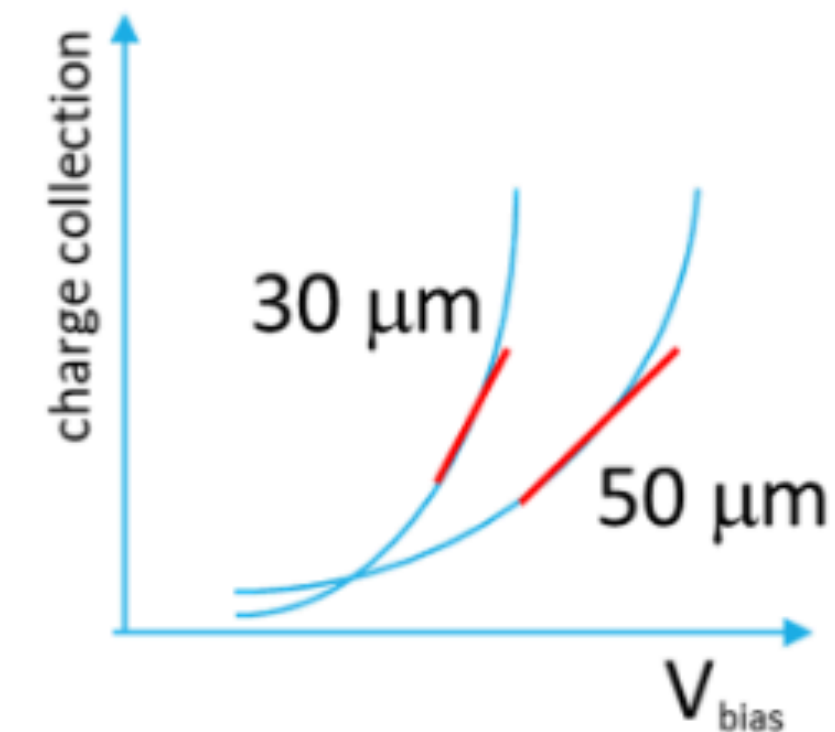
time res. \uparrow σ_t

noise jitter \uparrow σ_j

time walk \uparrow σ_{tw}

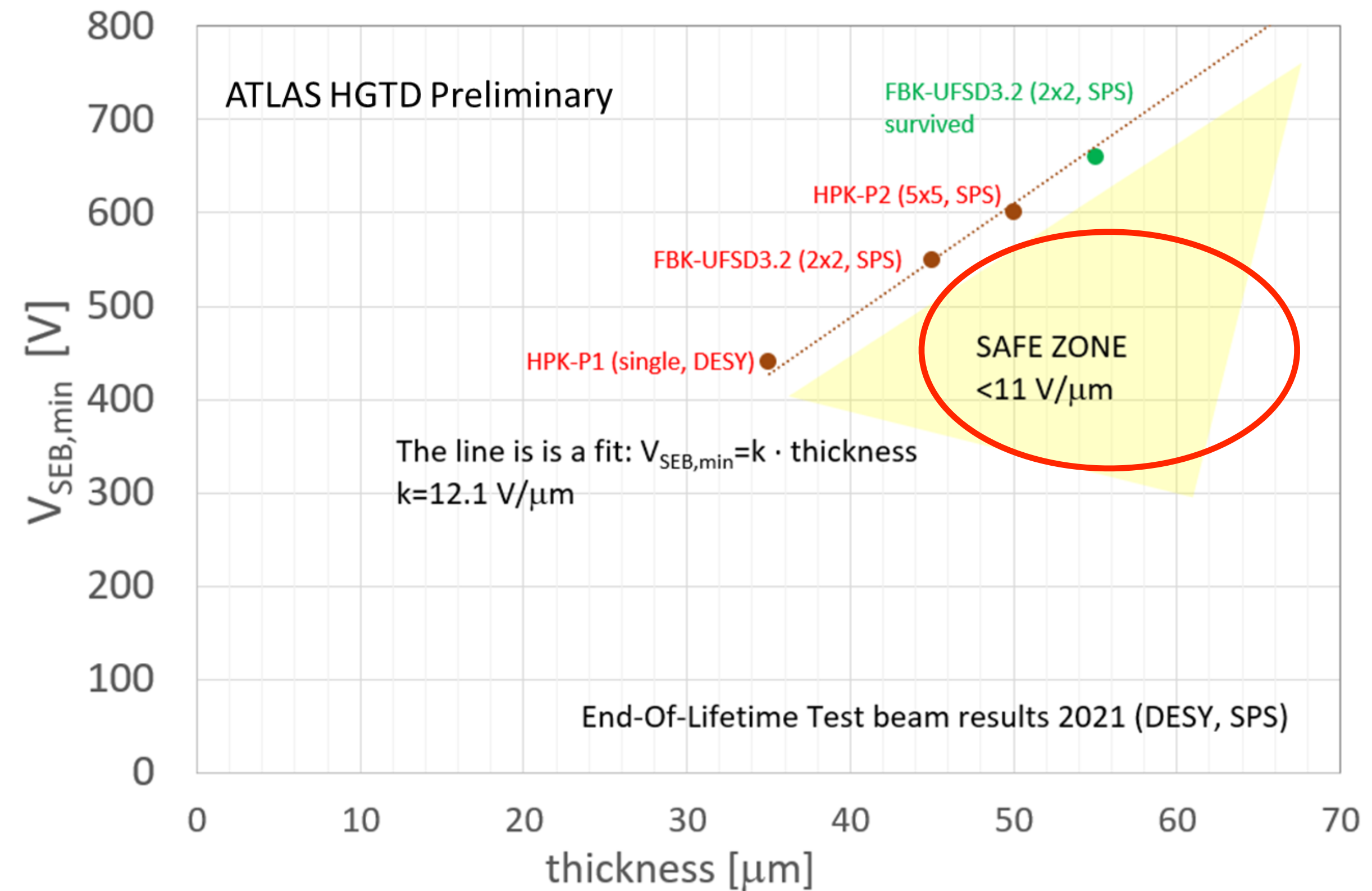
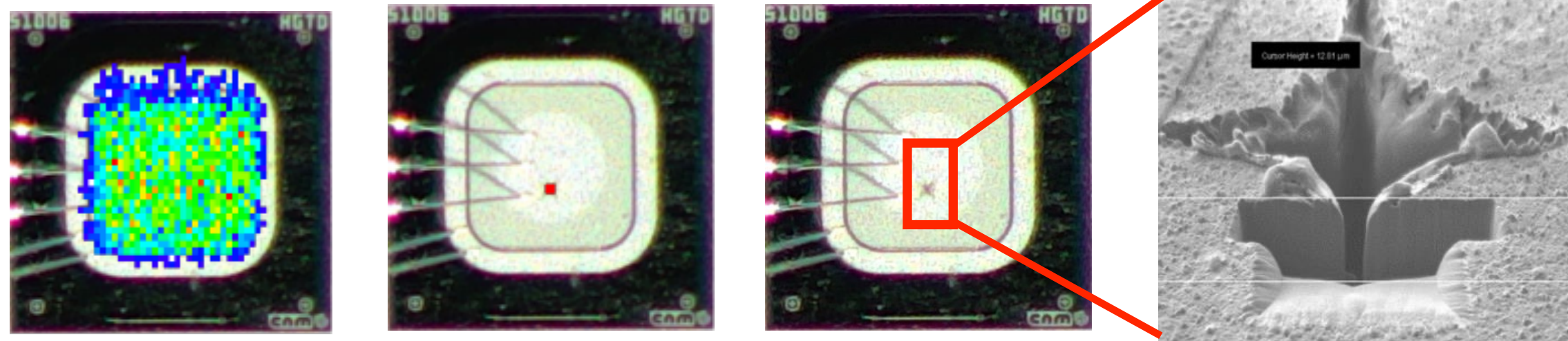
TDC \uparrow σ_{TDC}

$$\sigma_j = \frac{\sigma_n}{\left| \frac{dV}{dt} \right|} \approx \frac{\sigma_n}{\left| \frac{S}{\tau_p} \right|} = \frac{\tau_p}{S/N}$$



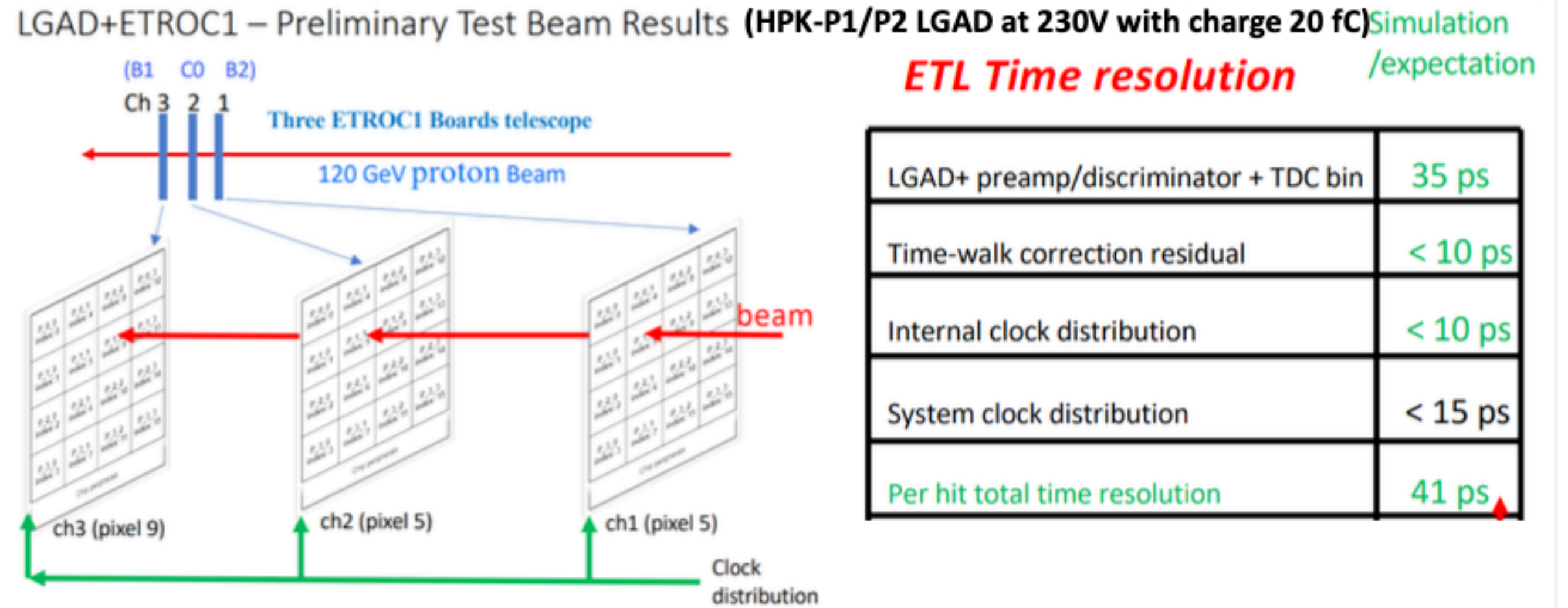
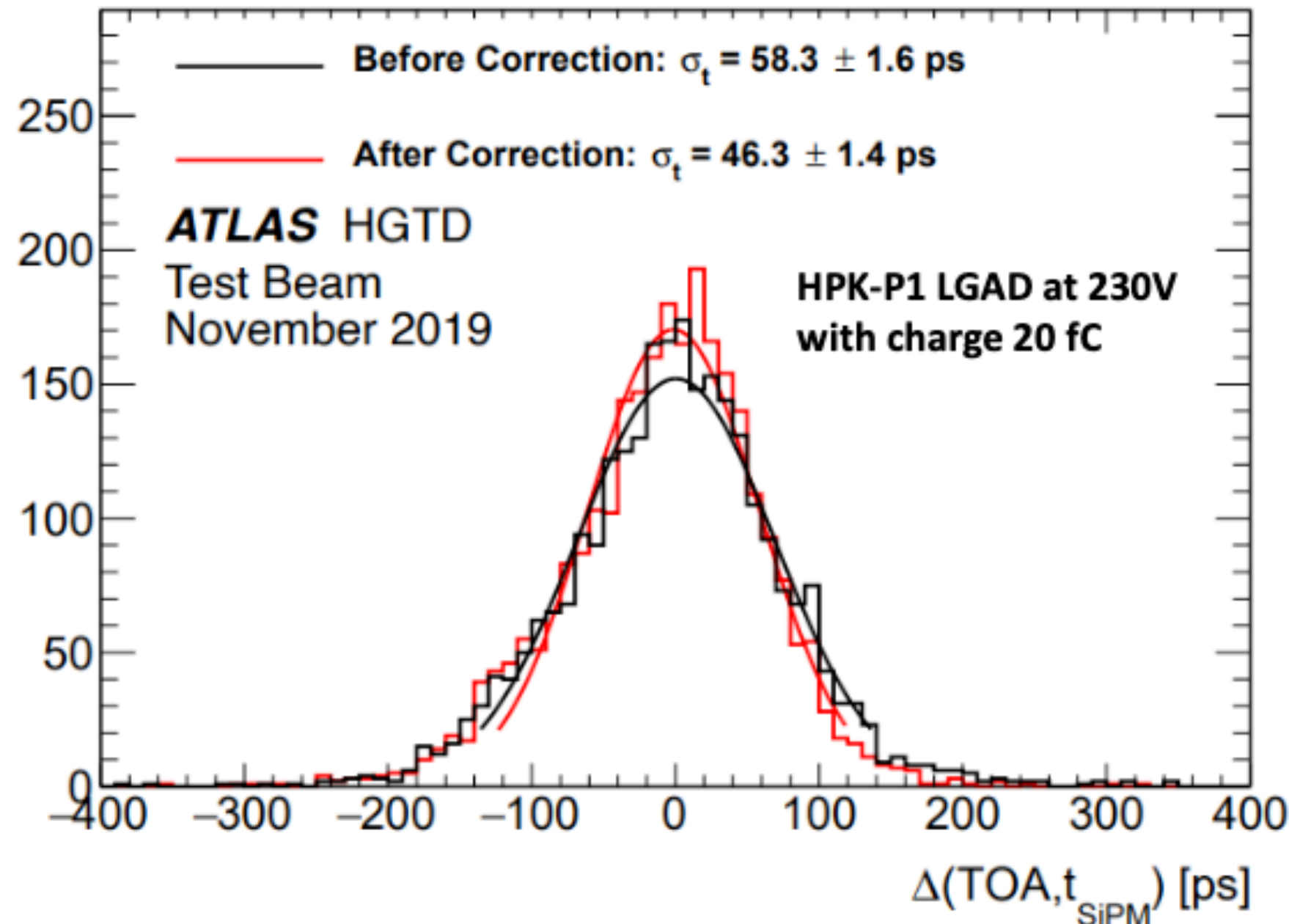
Single Event Burnout

- Single Event Burnout (SEB) - when heavily irradiated sensors (\sim end-of-life $2.5e15$ $n_{eq} \cdot cm^{-2}$) operated with high bias voltage
 - Not a problem if operated with lower voltage!
 - A single particle which deposits enough energy (\sim tens MeV) causes: conductive path leading to destructive breakdown
 - Confirmed & cross checked with R&D at CMS and RD50
 - Bias voltage safe from SEB: $< 11V/\mu m$ (i.e. $< \sim 550V$ for $50\mu m$)



ALTIROC1+LGAD TB performance

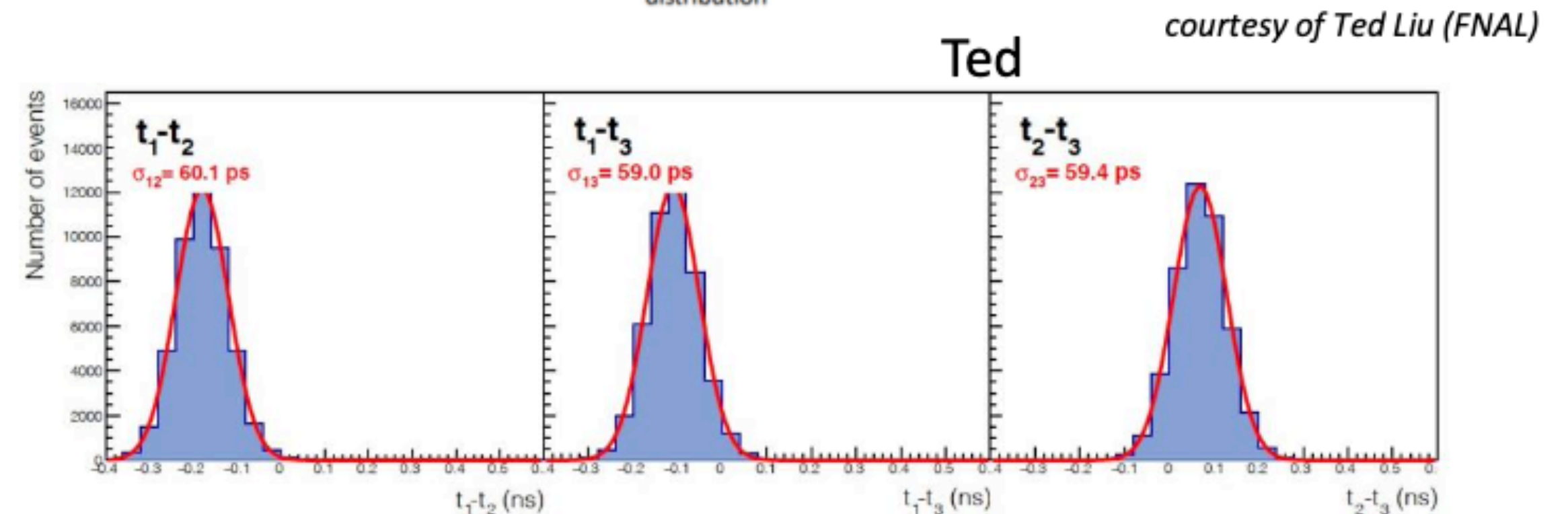
Slide from G. Kramberger



ETL Time resolution /expectation

LGAD+ preamp/discriminator + TDC bin	35 ps
Time-walk correction residual	< 10 ps
Internal clock distribution	< 10 ps
System clock distribution	< 15 ps
Per hit total time resolution	41 ps

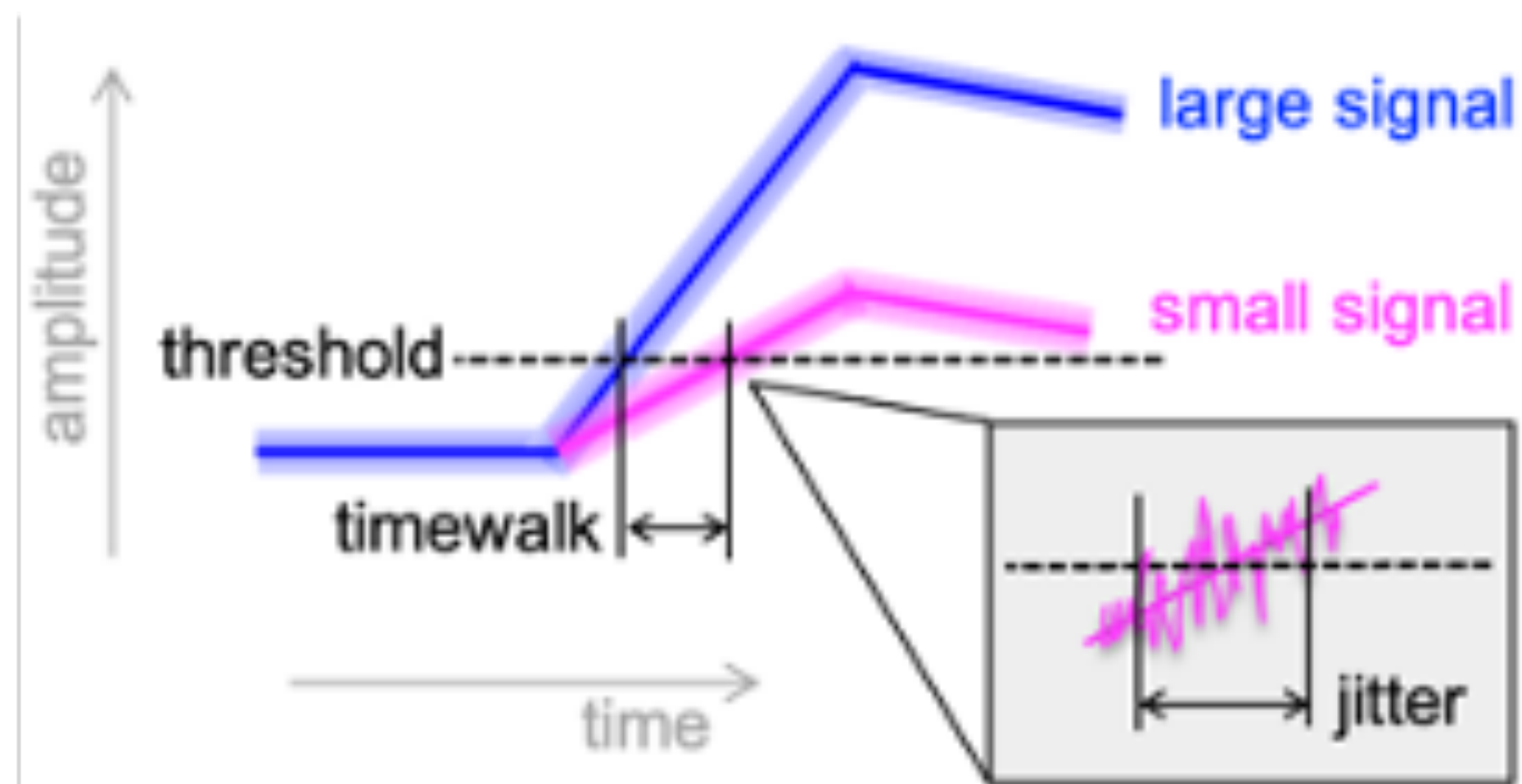
LGAD Landau	25 ps	the reason for part of the high jitter found 26 (known reasons)
Jitter+system/internal clock+time walk residual	37 ps	
TDC clock	7 ps	Total resolution: 36 ps (likely achievable for 20 fC)/ 70 ps for (4 fC)
Per hit total	46 ps	



Time Resolution: Jitter

Time Resolution is dominant by three components*

$$\sigma_t^2 = \sigma_{\text{TimeWalk}}^2 + \sigma_{\text{jitter}}^2 + \sigma_{\text{TDC}}^2$$



Jitter

- ▶ Amplitude fluctuations affect the exact threshold crossing time
- ▶ Fluctuations come from:
 - ▶ Thermal noise of the pre-amplifier
 - Large signal and/or high gain (power) mitigates this effect
 - ▶ Local fluctuations in the ionisation density

Clock and Time Measurement

Time Resolution is dominant by three components*

$$\sigma_t^2 = \sigma_{\text{TimeWalk}}^2 + \sigma_{\text{jitter}}^2 + \sigma_{\text{TDC}}^2$$

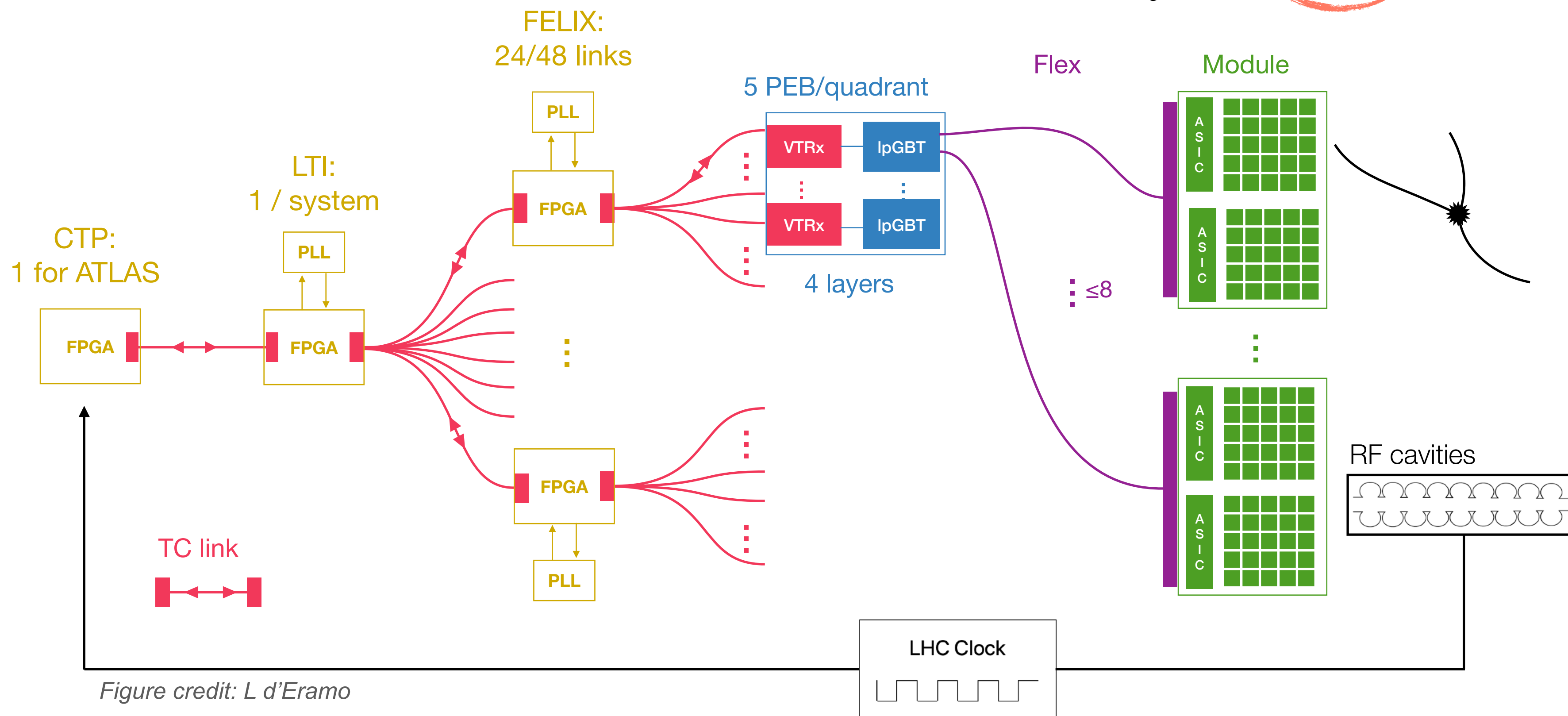


Figure credit: L d'Eramo

Clock

All time measurements are done w.r.t. a reference clock

Every hop introduce noise over the clock

Long cable can introduce time drift/wander (slow component) and jitter (fast component)

Actions:

- Compensation on hardware to ensure a precise clock distribution - TCLink
- Calibration of time offsets - challenging, *stay tuned* for our results!

* This equation has other variations, depending on how one categories the resource; the format here is commonly used in detector R&D community

4D Tracking: A Glimpse into the Future

To realise a **'real' 4D tracking**

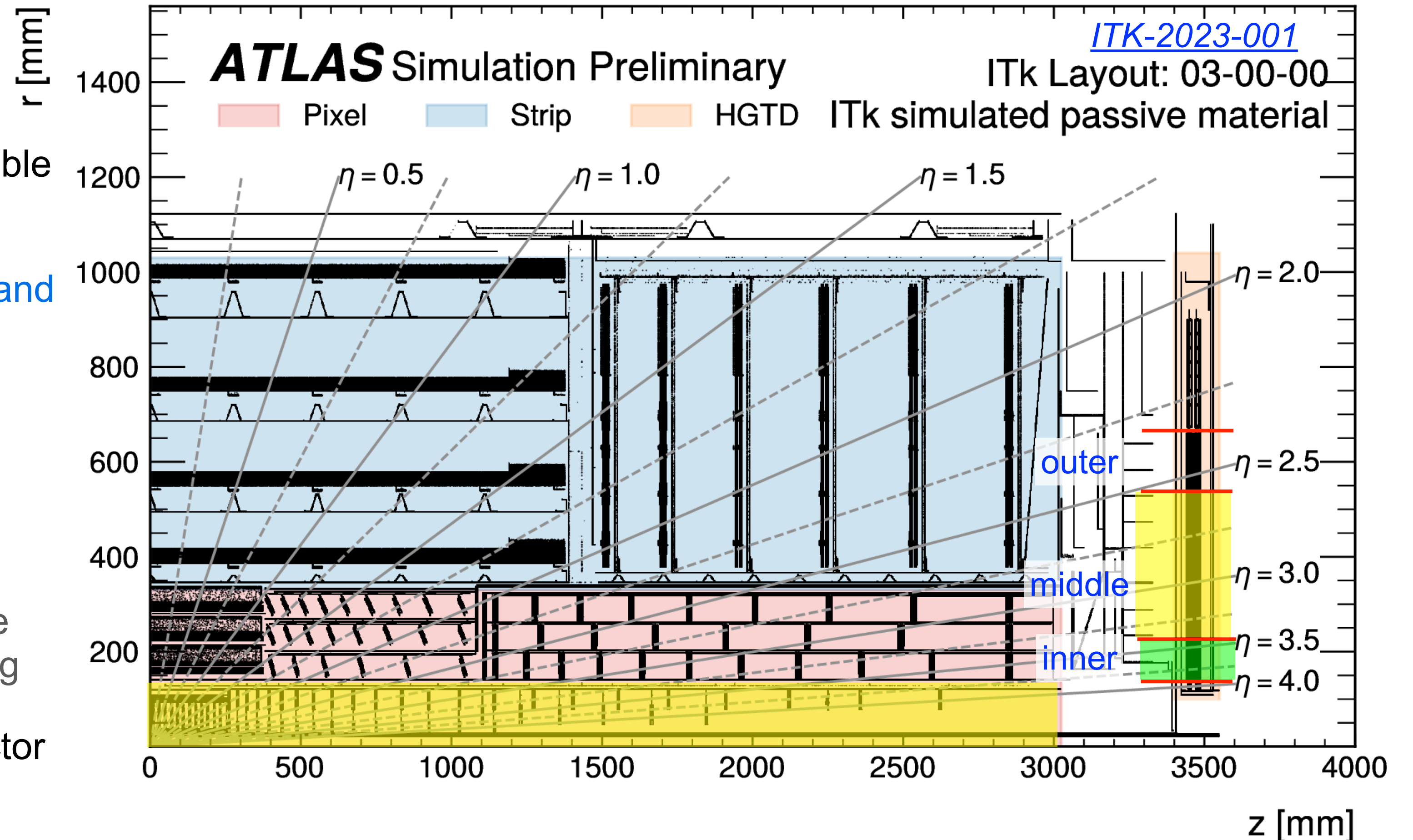
- ▶ To obtain temporal measurement on every track - with full 4π coverage

Replacement plan provides a chance to enable 4D tracking at HL-LHC:

- ▶ **Every 2 ab^{-1} :** *innermost ITK pixel layers and HGTD middle ring* to be replaced
- ▶ **Every 1 ab^{-1} :** HGTD inner ring to be replaced

Challenges:

- ▶ *Novel 4D tracking algorithms to built:* use time information in track finding and fitting
- ▶ Unknown impact of 4D tracking on detector geometry choice



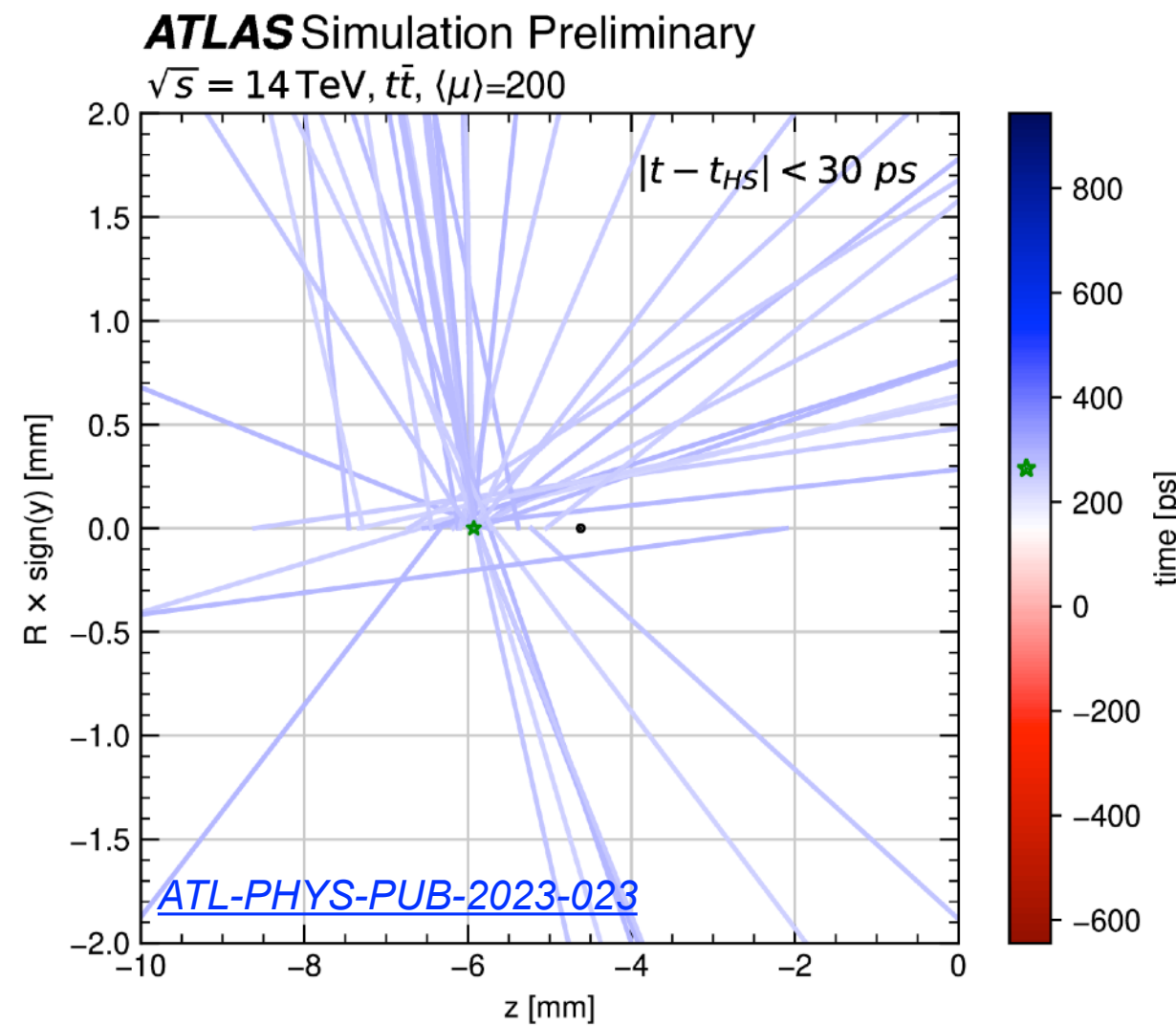
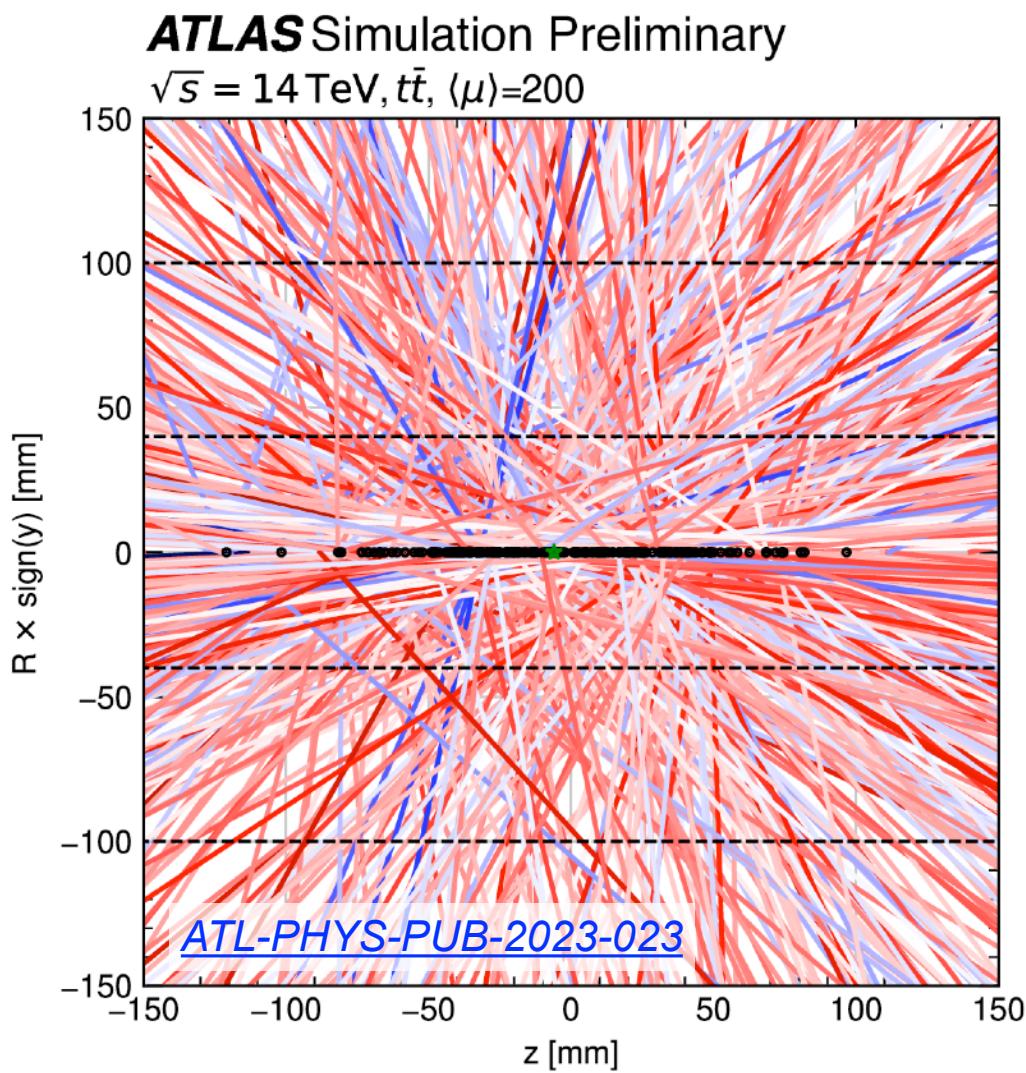
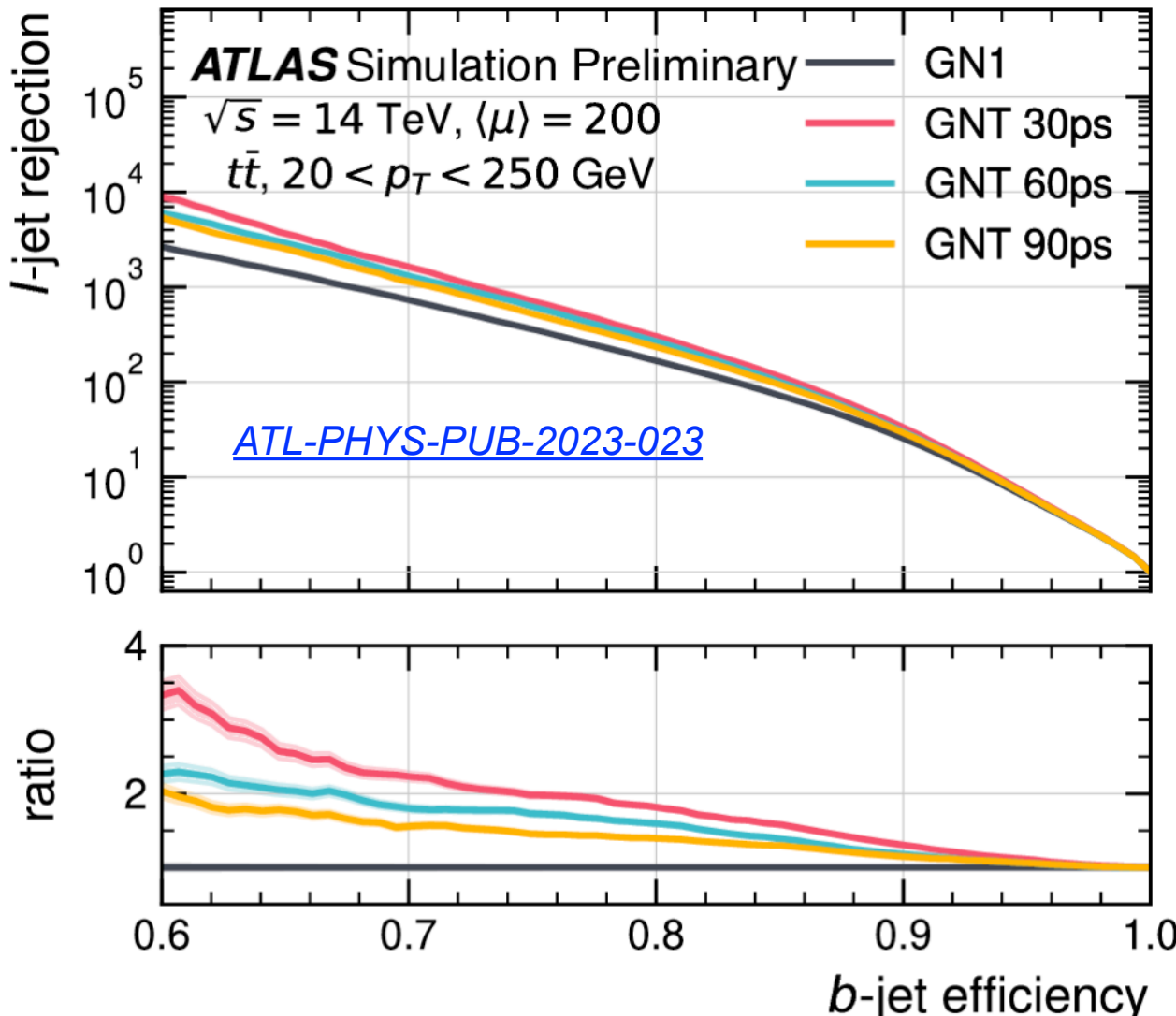
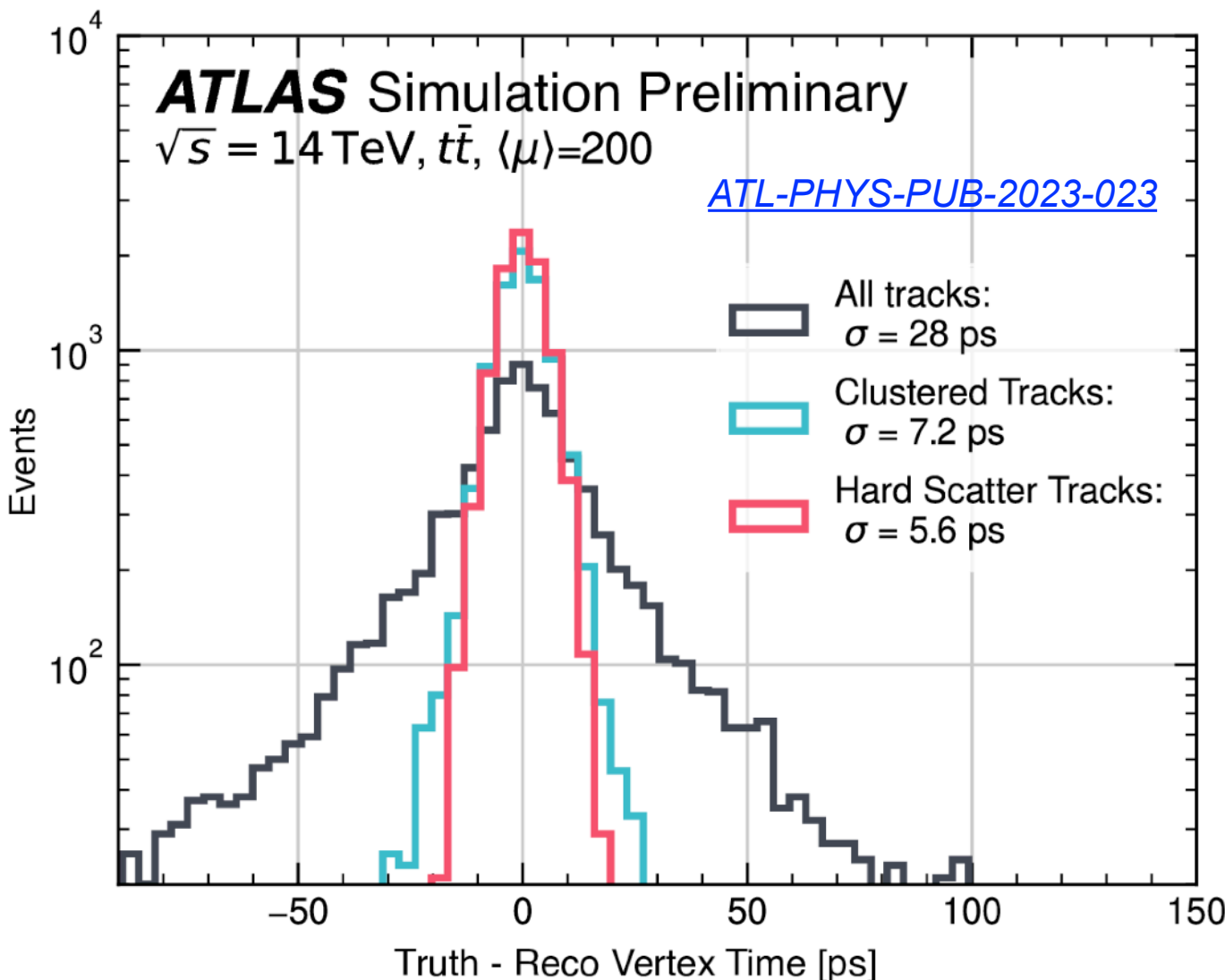
4D Tracking: A Glimpse into the Future

Pioneer simulation studies have been made using simulations

- Time of every vertex (incl. central vertices) can be reconstructed

Performance potentials:

- Strong pileup suppression
- Full η coverage for a better HS vertex t_0 determination



Pioneer simulation studies have been made using simulations

- ▶ B-tagging improved up to a factor 3.5 using timing information also in the central region